



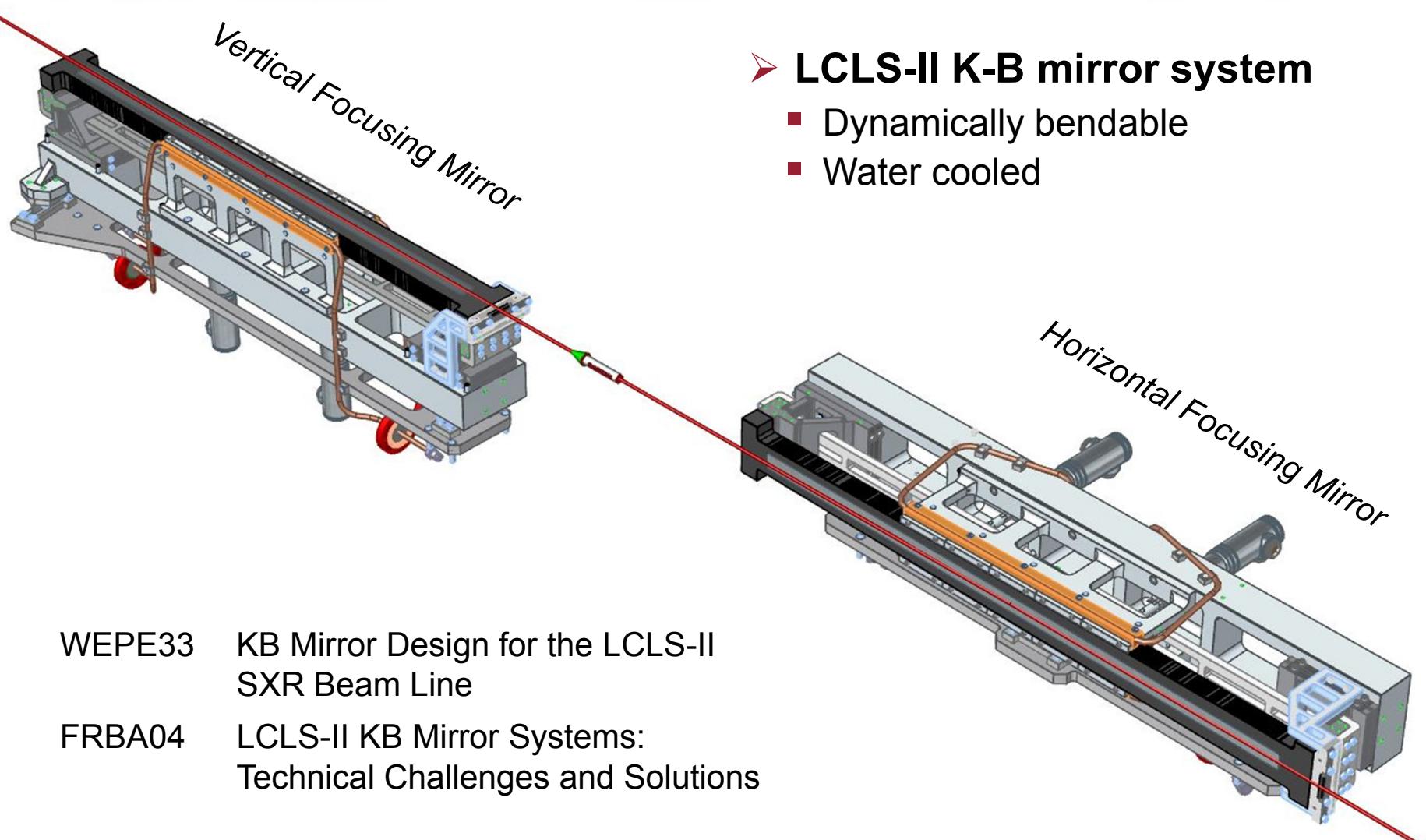
# Minimization of mechanical constraint effects of Eutectic GaIn as thermal interface

*L. Zhang, D. Cocco, N. Kelez, J. James, D.S. Morton*

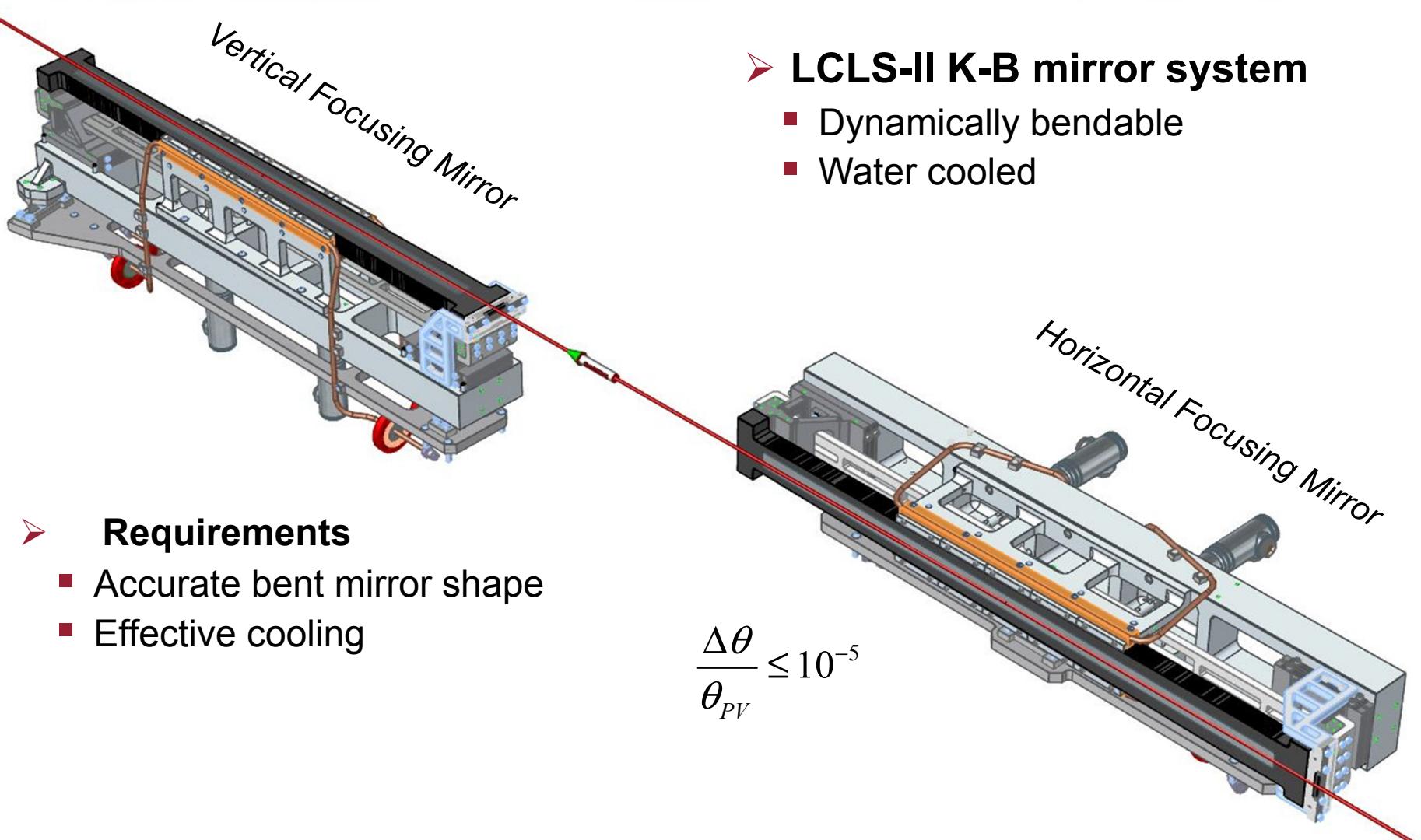
*LCLS, SLAC National Accelerator Laboratory*

*2575 Sand Hill Road, Menlo Park, CA, 94025, United States*

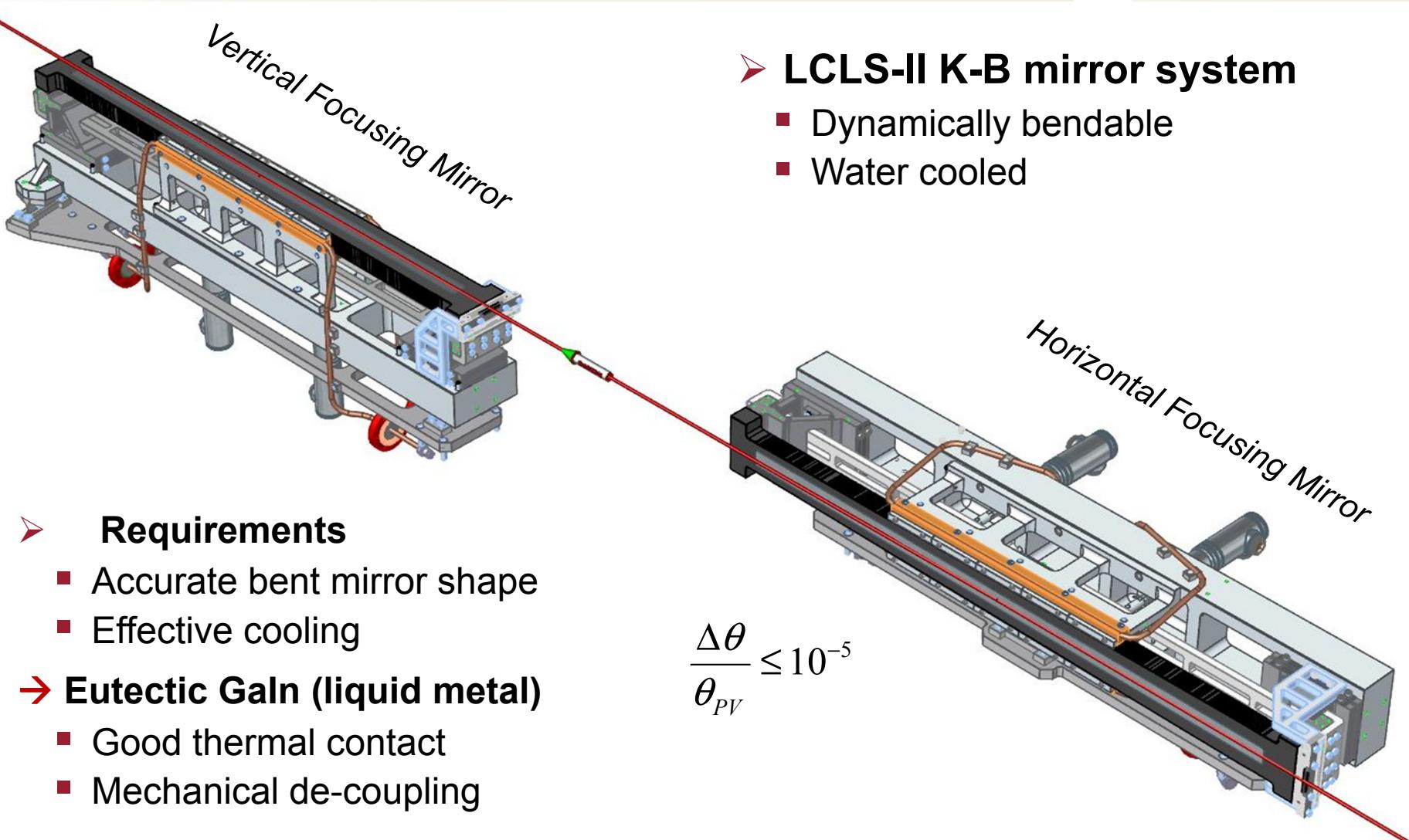
# Background



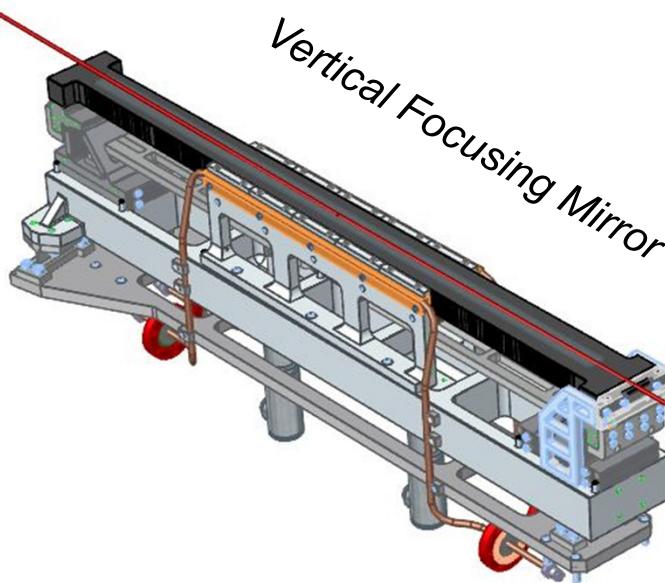
# Background



# Background

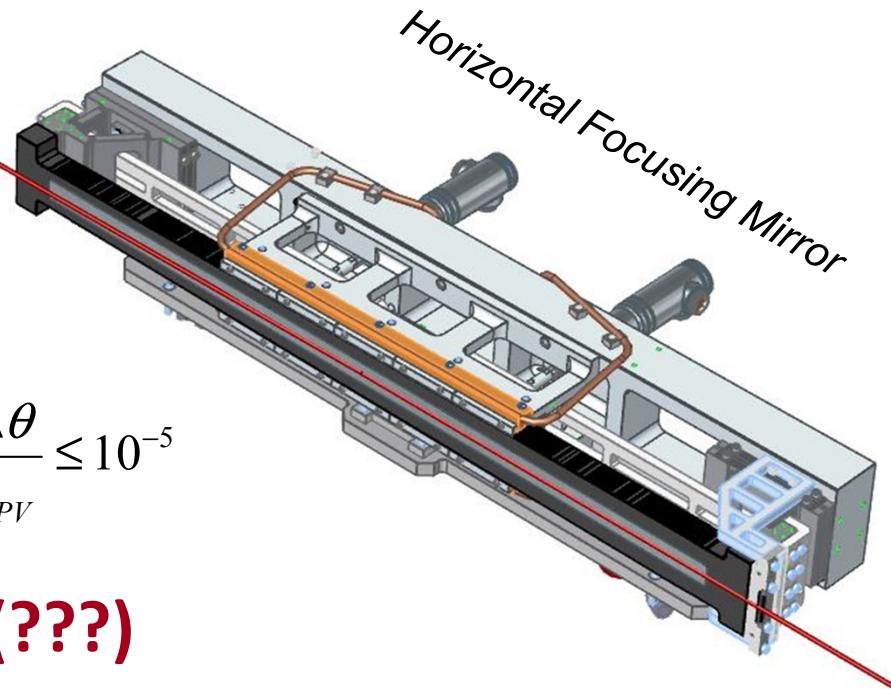


# Background



## ➤ LCLS-II K-B mirror system

- Dynamically bendable
- Water cooled



## ➤ Requirements

- Accurate bent mirror shape
- Effective cooling

## → Eutectic GaIn (liquid metal)

- Good thermal contact

## ■ Mechanical de-coupling (???)

$$\frac{\Delta\theta}{\theta_{PV}} \leq 10^{-5}$$

# Eutectic Gallium-Indium (eGaln)

SLAC

- eGaln: 75.5% Gallium (29.76°C)  
24.5% Indium (156.6°C)  $T_{\text{melting}} = 15.7^{\circ}\text{C}$



- Thermal interface
  - Thermal conductance  $> 10^5 \text{ W/m}^2\text{.K}$ , ~ 10 times better than Indium foil
  - Interface or trough / bath for indirect cooling of the X-ray mirrors

# Eutectic Gallium-Indium (eGaln)

SLAC

- eGaln: 75.5% Gallium (29.76°C)  
24.5% Indium (156.6°C)  $T_{\text{melting}} = 15.7^{\circ}\text{C}$



- Thermal interface
  - Thermal conductance  $> 10^5 \text{ W/m}^2\cdot\text{K}$ , ~ 10 times better than Indium foil
  - Interface or trough / bath for indirect cooling of the X-ray mirrors
- Mechanical properties

# Eutectic Gallium-Indium (eGaN)

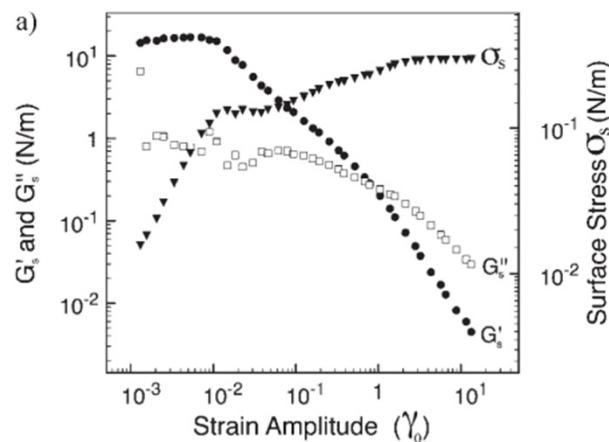
SLAC

- eGaN: 75.5% Gallium (29.76°C)  
24.5% Indium (156.6°C)

$$T_{\text{melting}} = 15.7^\circ\text{C}$$



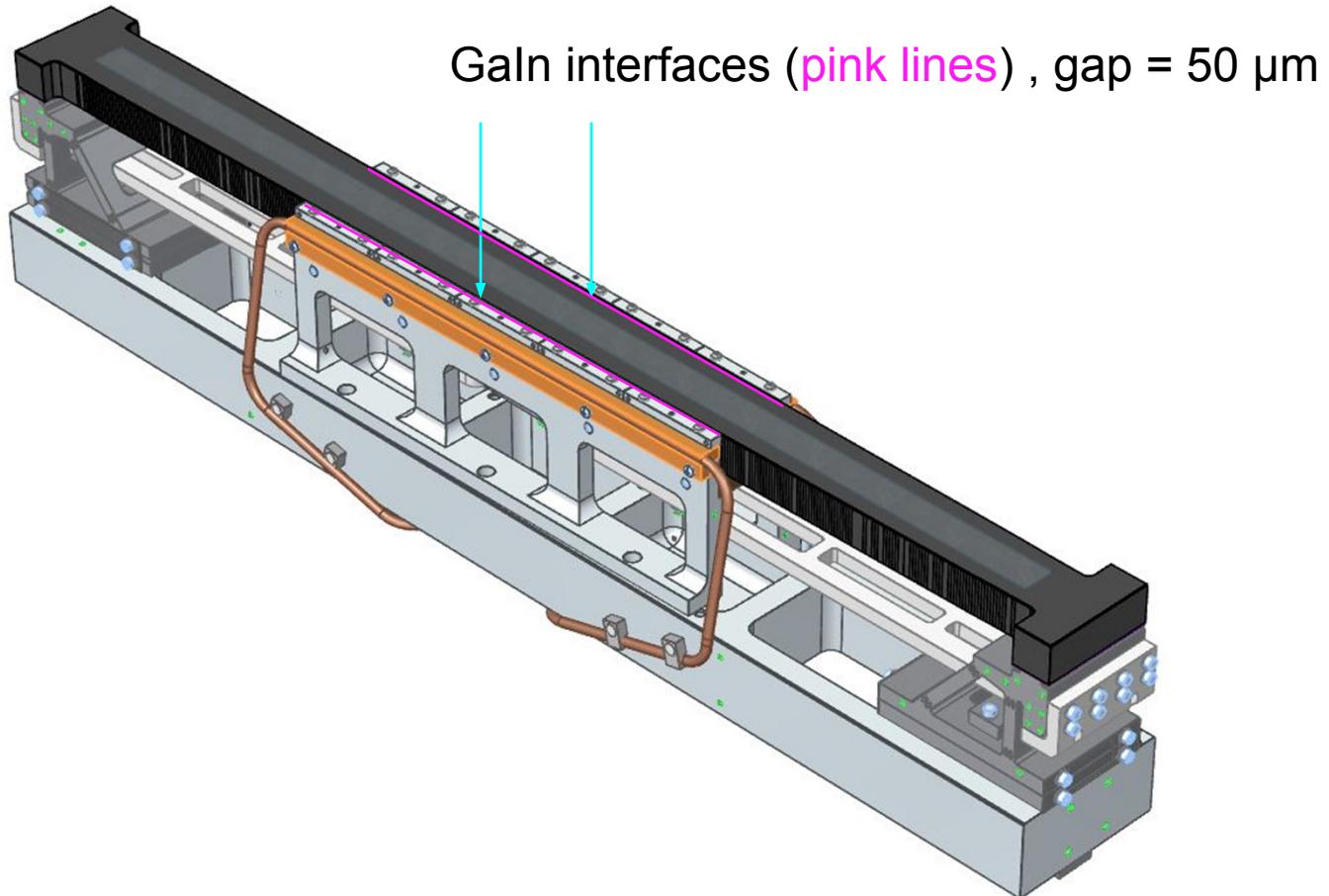
- Thermal interface
  - Thermal conductance  $> 10^5 \text{ W/m}^2\cdot\text{K}$ , ~ 10 times better than Indium foil
  - Interface or trough / bath for indirect cooling of the X-ray mirrors
- Mechanical properties
  - Bulk viscosity  $\sim 2 \text{ mPa}\cdot\text{s}$  ( $2\mu_{\text{water}}$ )
  - Modulus ??
  - Thin skin (oxides of Ga)



Dickey, *ACS Appl. Mater. Interfaces* 2014, 6, 18369–18379

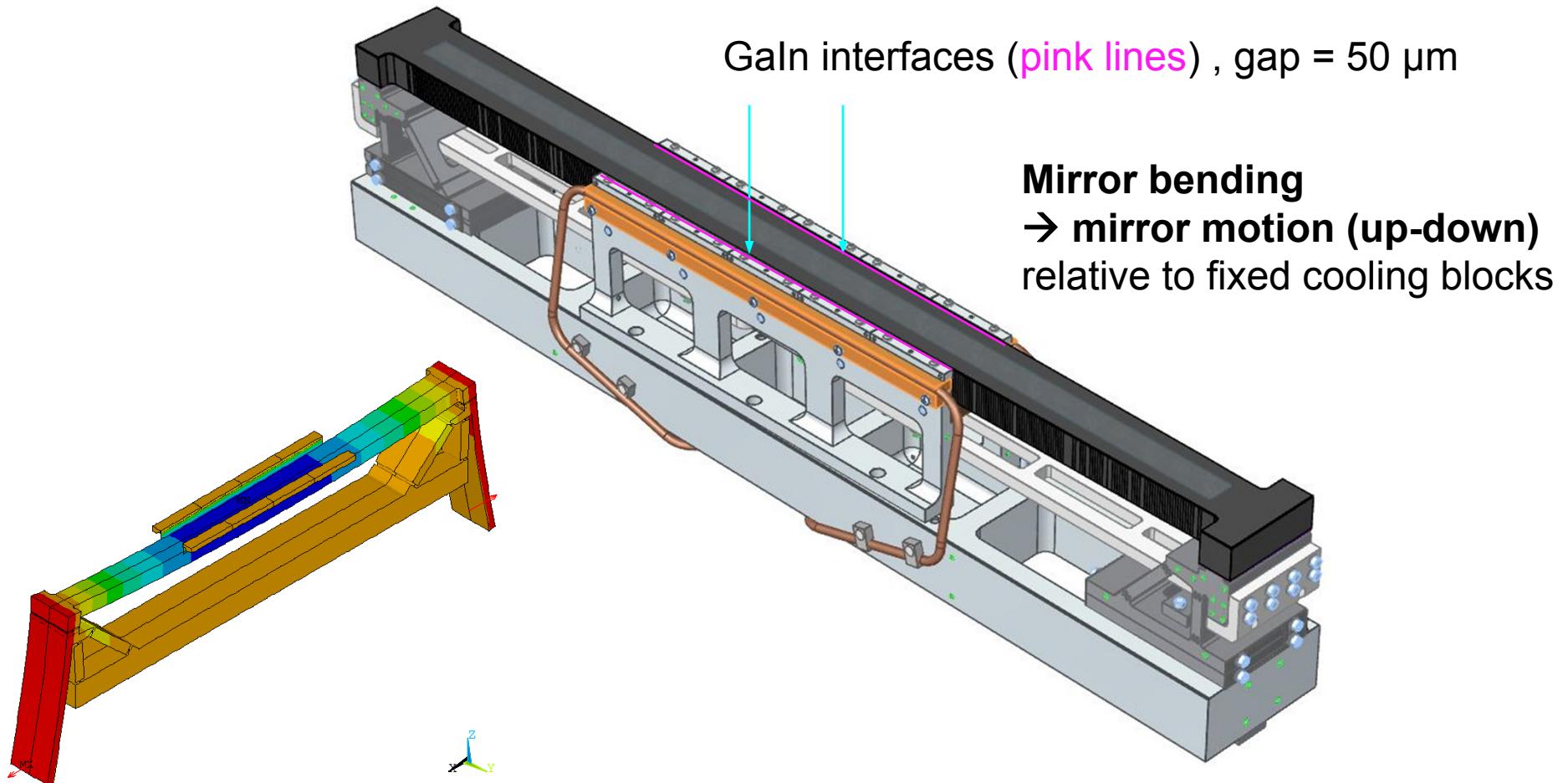
# Eutectic Galn as thermal contact interface

SLAC



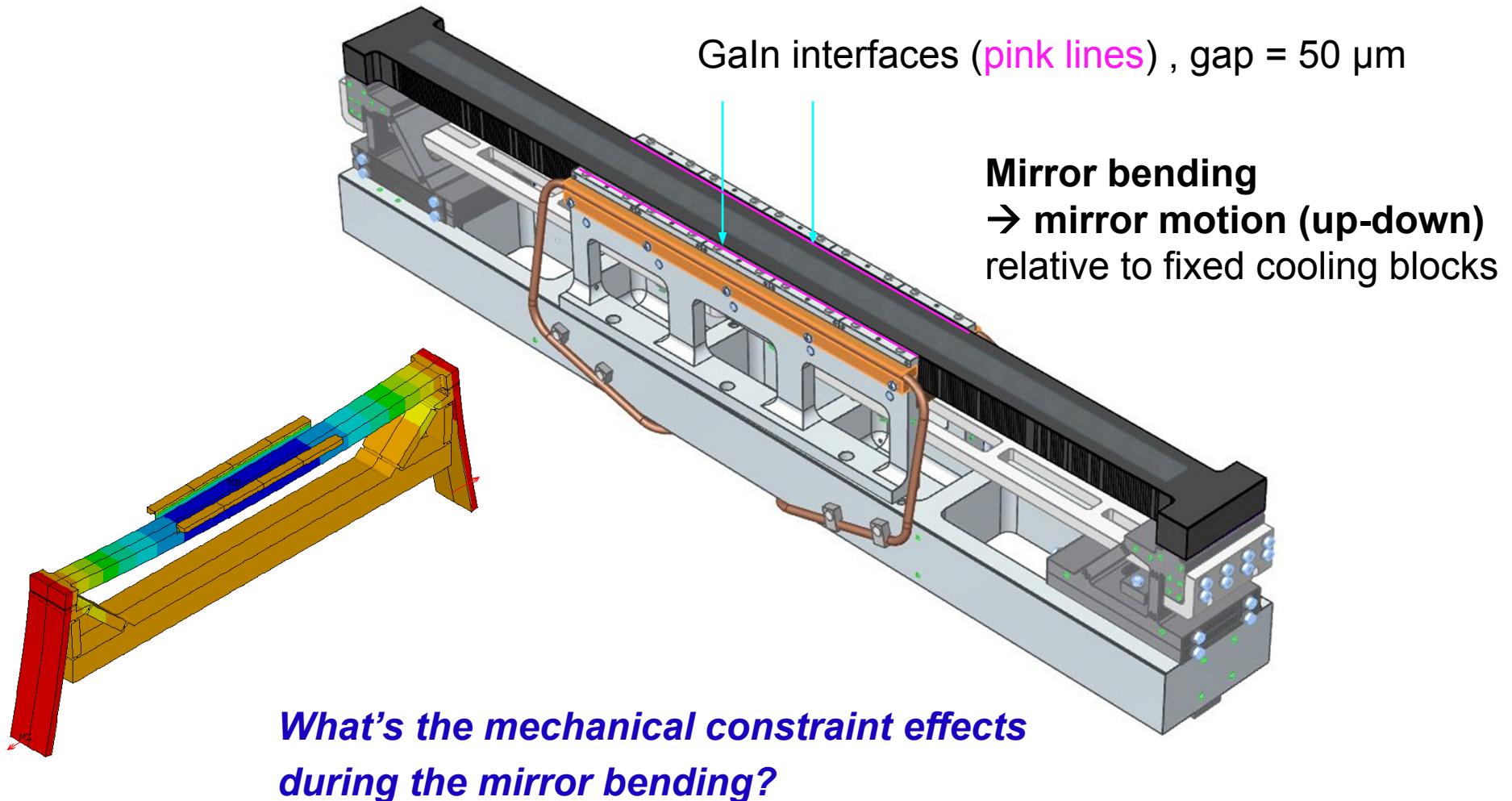
# Eutectic GaIn as thermal contact interface

SLAC



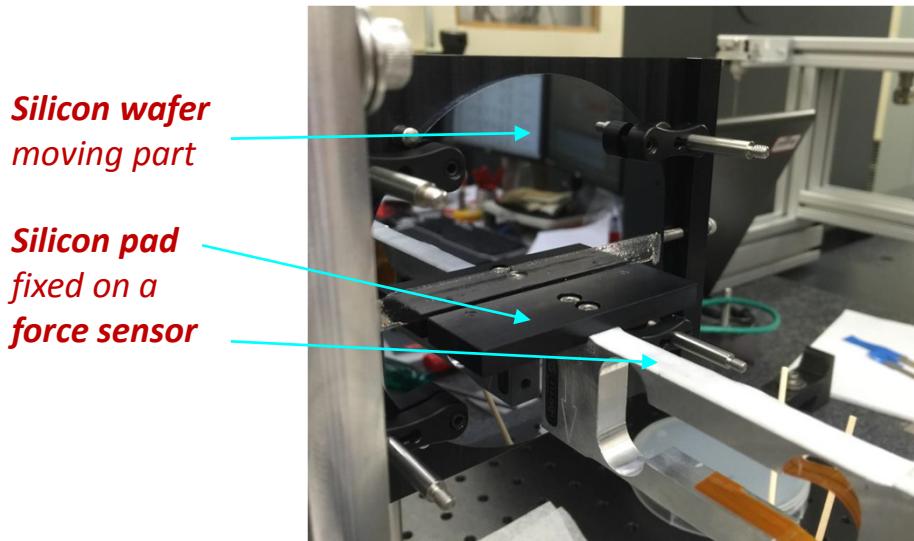
# Eutectic GaIn as thermal contact interface

SLAC



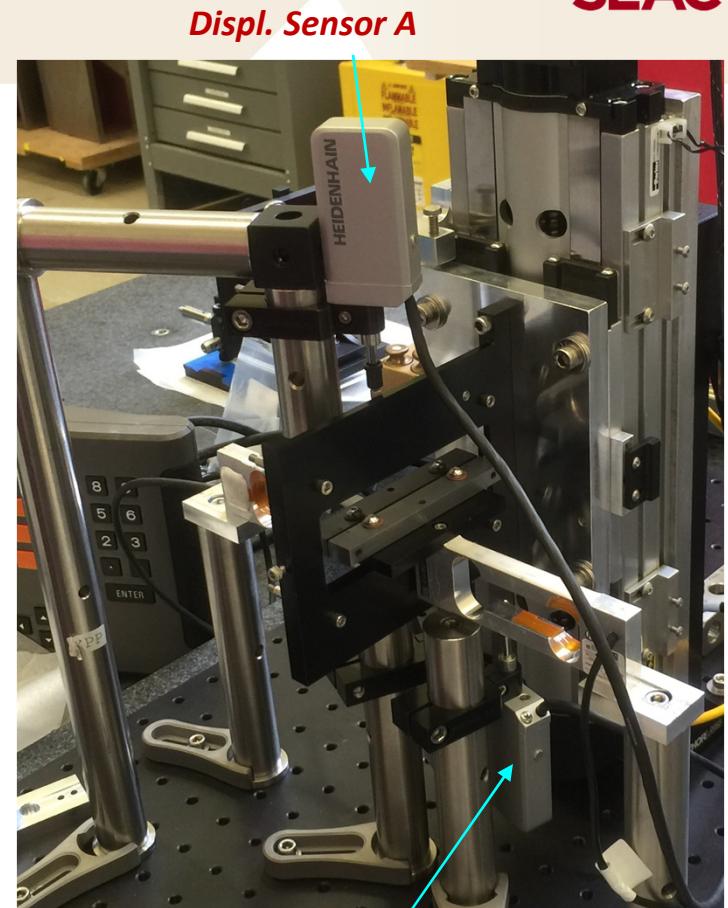
# GaN test Setup

- Si-wafer ( $D=4"$ ,  $t = 4 \text{ mm}$ , both side polished)
- GaN gap: (51, 102, 152, 203, 254  $\mu\text{m}$ )



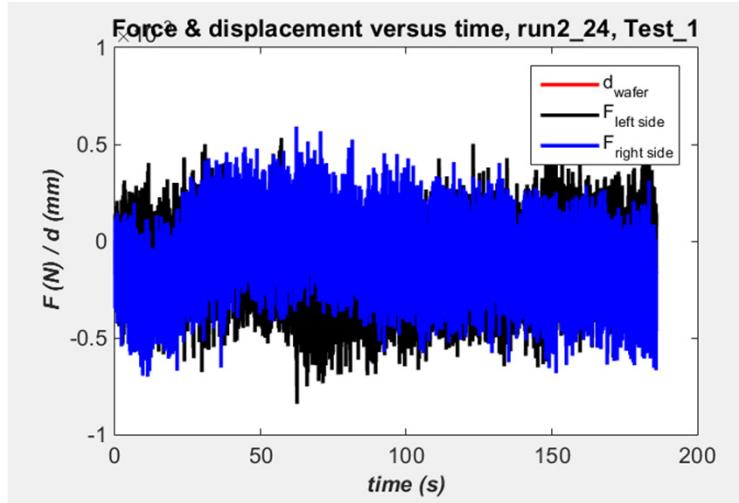
## ➤ Measurements

- Displacement of Si-wafer  $d_{\text{wafer}}$
- Forces of Si-pads on  
Left side and Right side:  $F_L, F_R$
- Relative displacement between wafer and pads:  $d_{\text{pad}} = d_{\text{wafer}} - (F - F_0)/k_{FG}$
- Force gauge stiffness:  $k_{FG} = 10.57 \text{ N/mm}$



# GaN test Setup – measurement accuracy

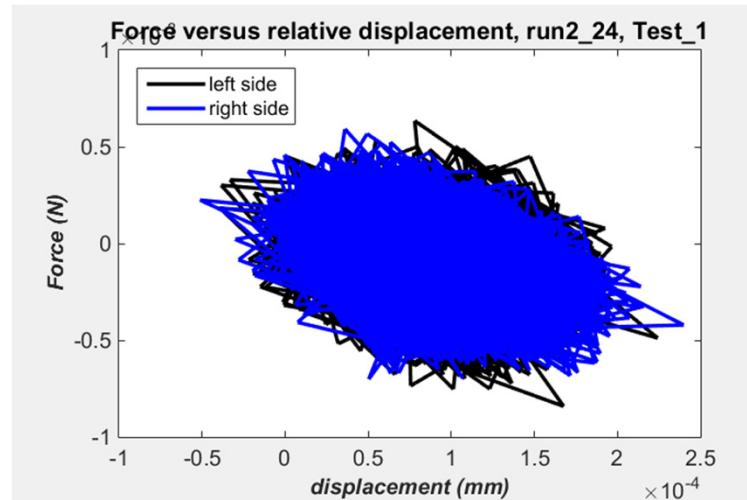
- Force & displacement measured when there is no motion



$\text{gap} = 100 \mu\text{m}$

$$\begin{aligned}\varepsilon_d &= \pm 0.15 \mu\text{m} \\ \varepsilon_F &= \pm 0.7 \text{ mN}\end{aligned}$$

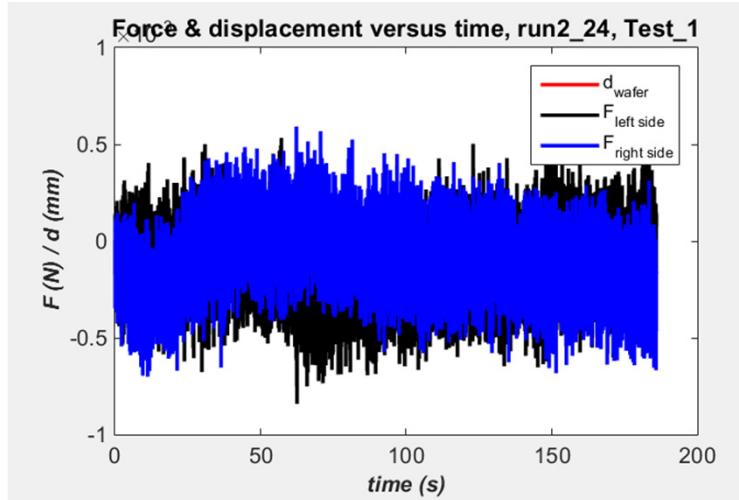
Sensors accuracy:  
0.2  $\mu\text{m}$ , 0.2 mN



# GaN test Setup – measurement accuracy

SLAC

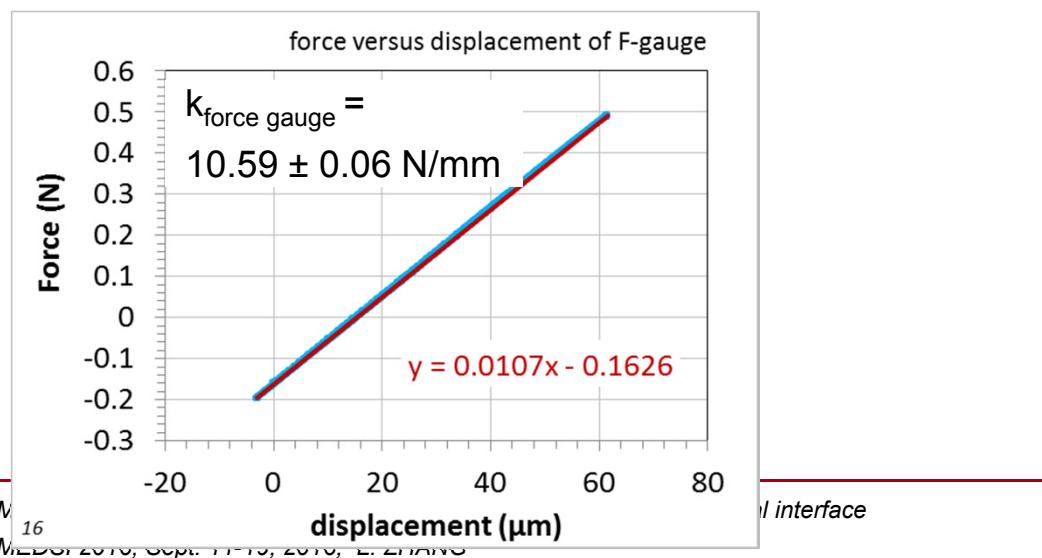
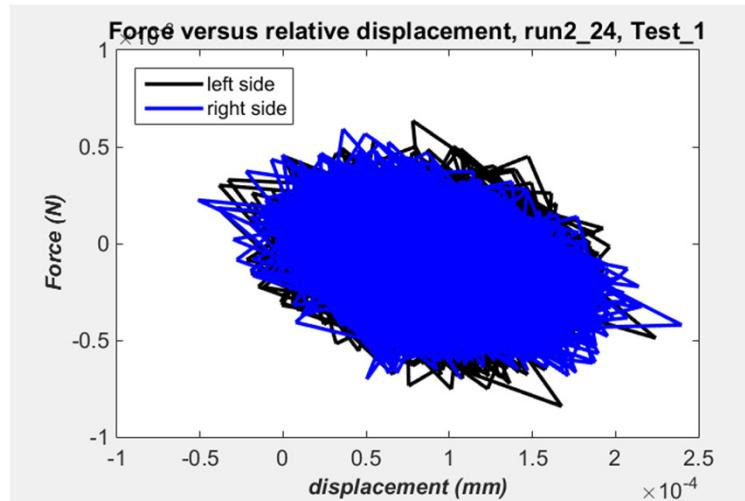
- Force & displacement measured when there is no motion



$$\text{gap} = 100 \mu\text{m}$$

$$\varepsilon_d = \pm 0.15 \mu\text{m}$$
$$\varepsilon_F = \pm 0.7 \text{ mN}$$

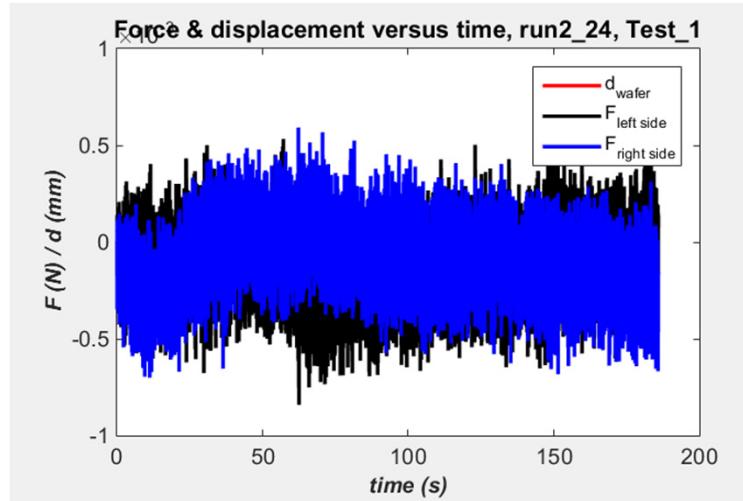
Sensors accuracy:  
0.2  $\mu\text{m}$ , 0.2 mN



# GaN test Setup – measurement accuracy

SLAC

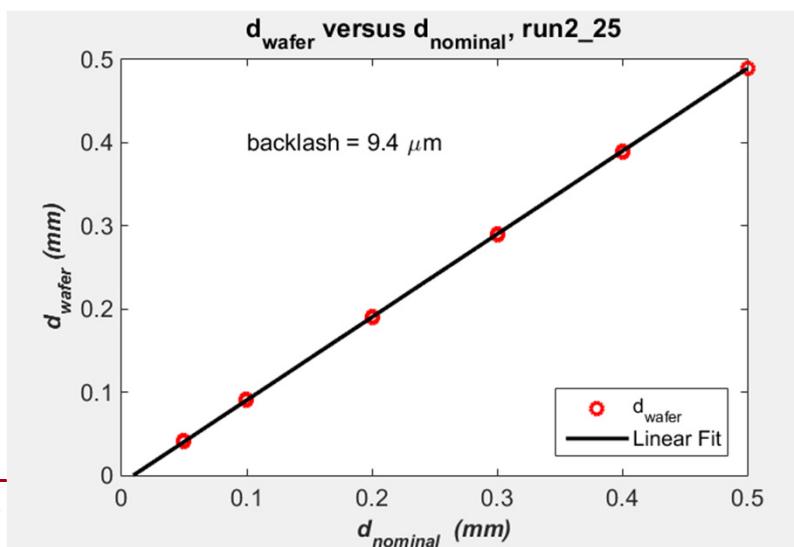
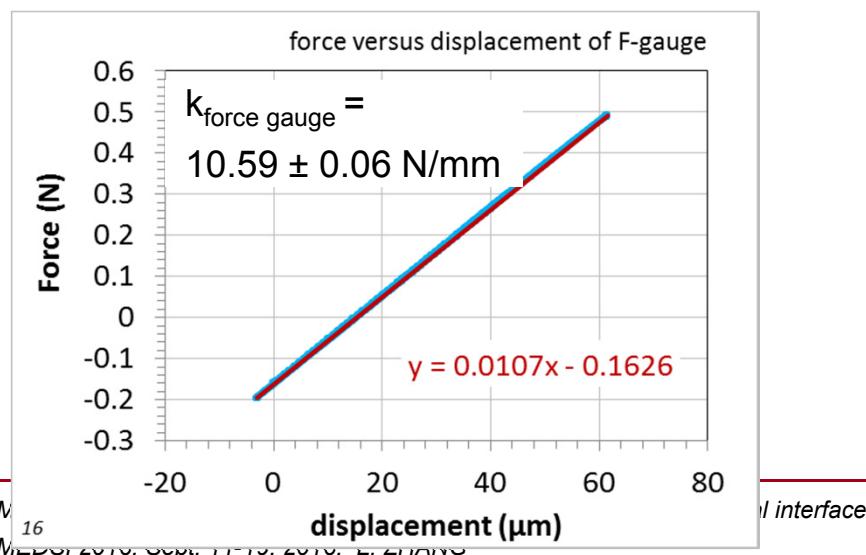
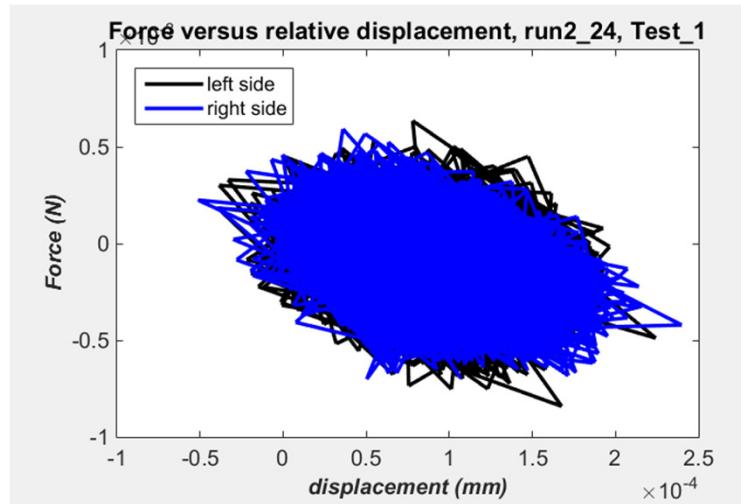
- Force & displacement measured when there is no motion



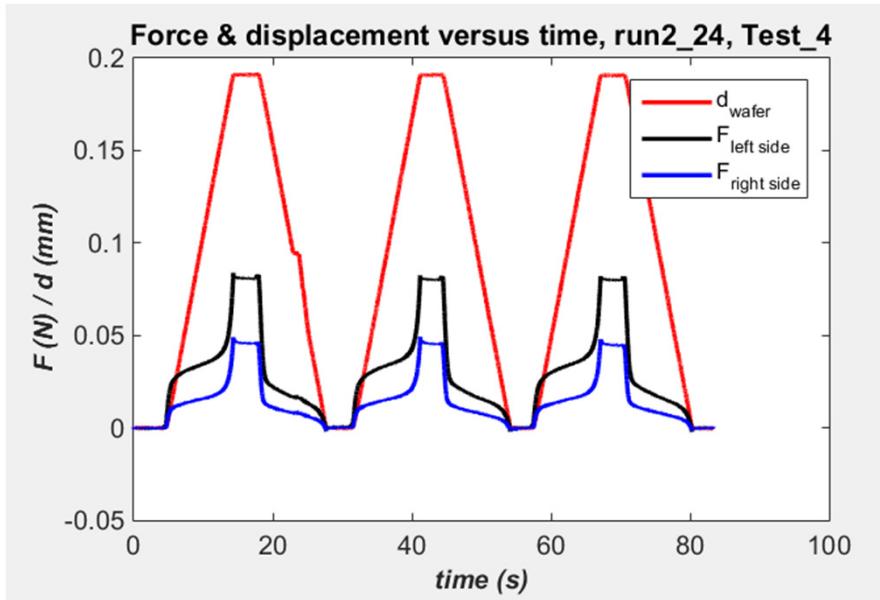
$$\text{gap} = 100 \mu\text{m}$$

$$\epsilon_d = \pm 0.15 \mu\text{m}$$
$$\epsilon_F = \pm 0.7 \text{ mN}$$

Sensors accuracy:  
0.2  $\mu\text{m}$ , 0.2 mN



# GaN Test results – Repeatability

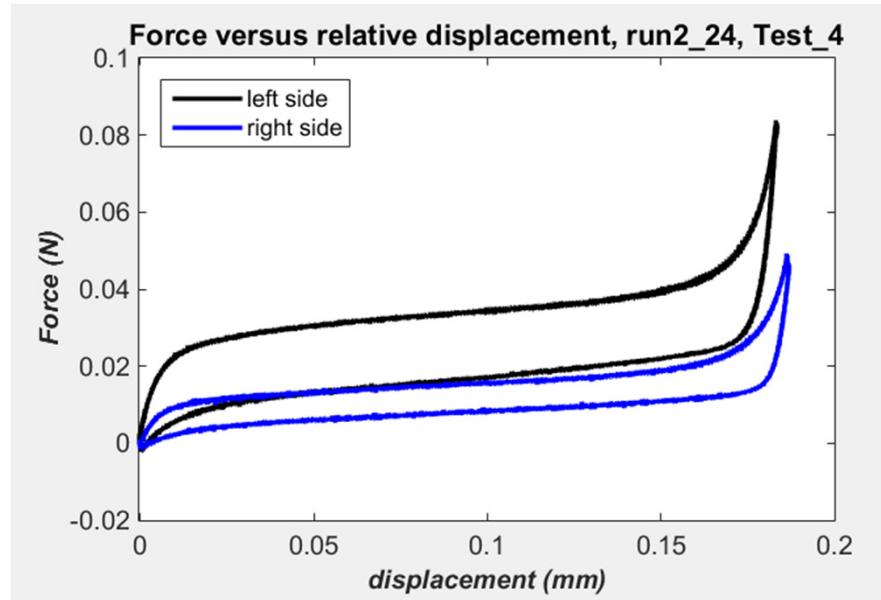
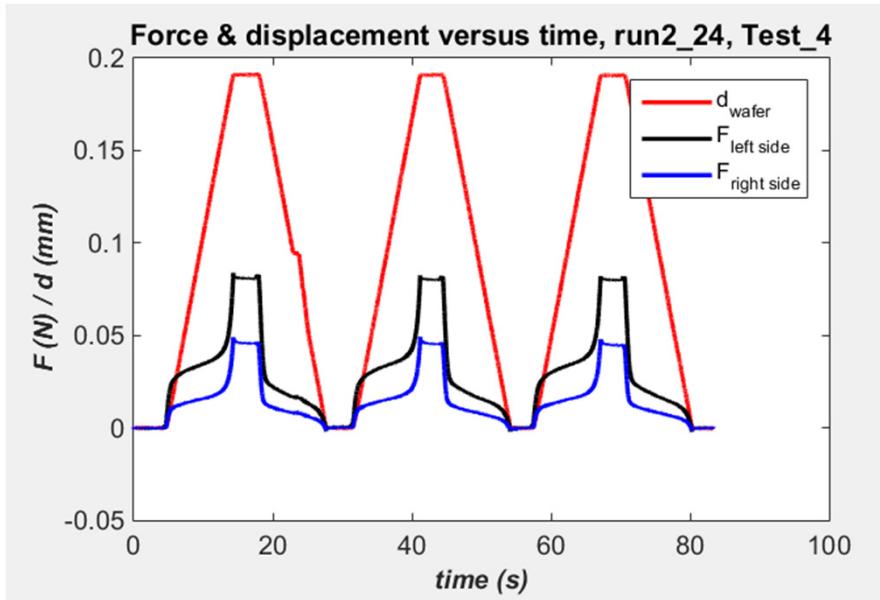


- GaN gap =  $100 \mu\text{m}$
- Si-wafer displacement  $d_{\text{wafer}} = 200 \mu\text{m}$ , at speed  $20 \mu\text{m/s}$
- 3 – cycles measurements → Good repeatability

# GaN Test results – Repeatability

SLAC

Share stress  $\sim F/A_{\text{contact}}$

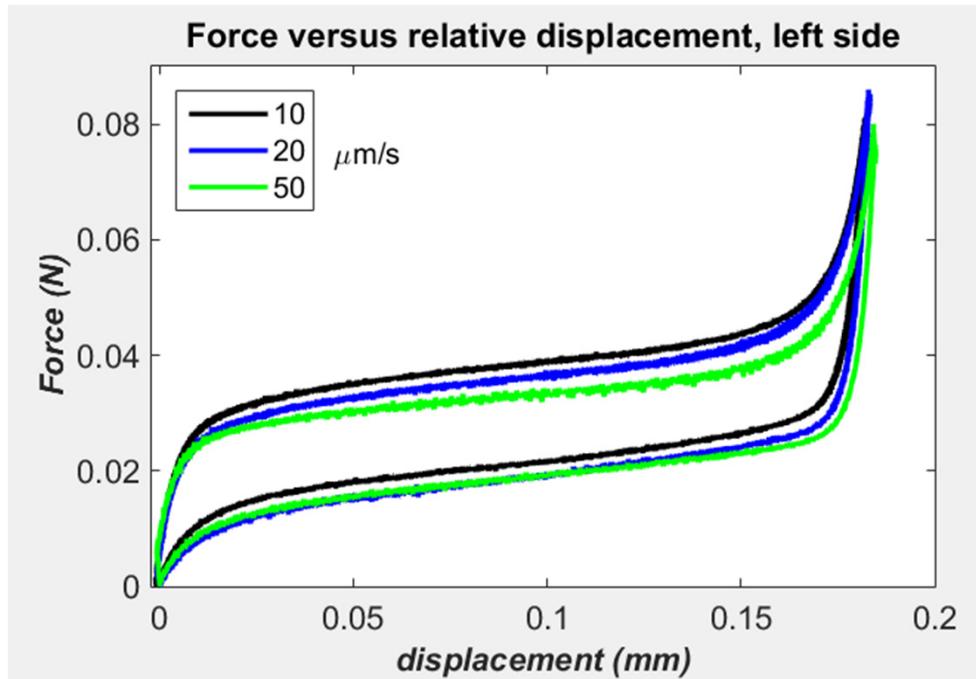


Share strain  $\sim d/\text{gap}_{\text{GaN}}$

- GaN gap = 100  $\mu\text{m}$
- Si-wafer displacement  $d_{\text{wafer}} = 200 \mu\text{m}$ , at speed 20  $\mu\text{m/s}$
- 3 – cycles measurements → Good repeatability

# GaN Test results – at different speed of displacement

- Si-wafer displacement  $d_{\text{wafer}} = 200 \mu\text{m}$ , at speed 10, 20, 50  $\mu\text{m/s}$
- 3 cycles measurements per speed → Repeatable

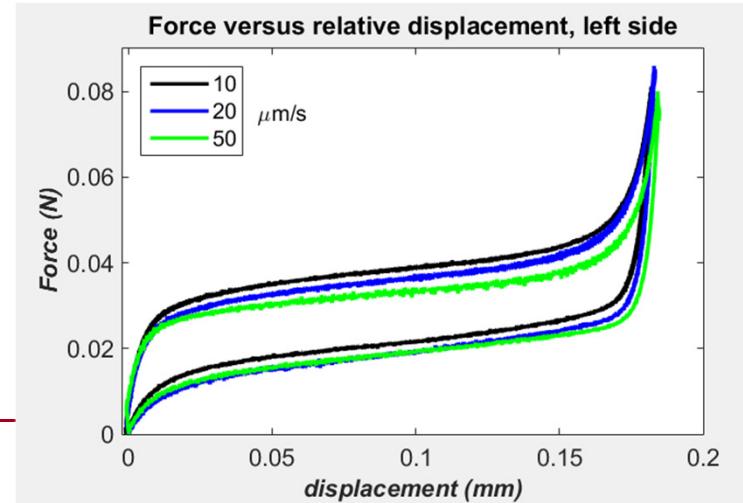


- Speed 20  $\mu\text{m/s}$  is mostly used in other measurements

# Which type of material model ?

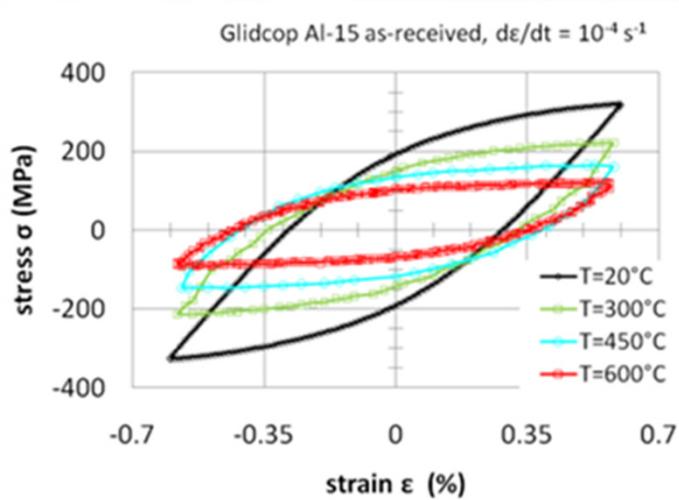
SLAC

**Shear strain:100% ~ 400%**



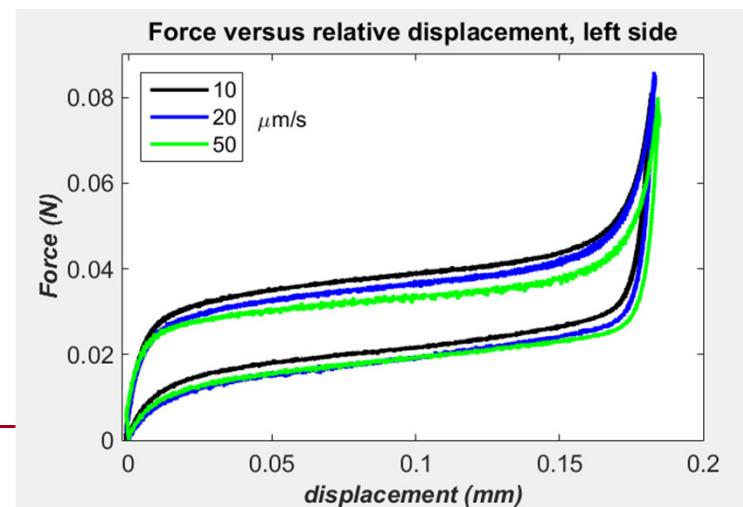
# Which type of material model ?

SLAC



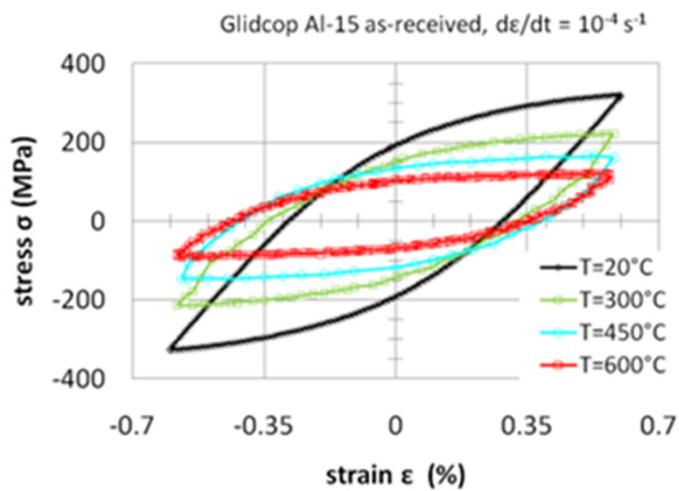
**ElastoViscoPlasticity**  
Glidcop Al-15 at  
different temperature

**Shear strain:100% ~ 400%**



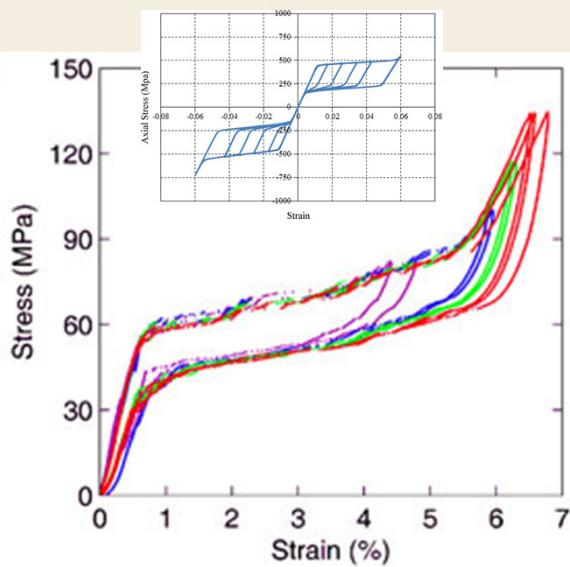
# Which type of material model ?

SLAC

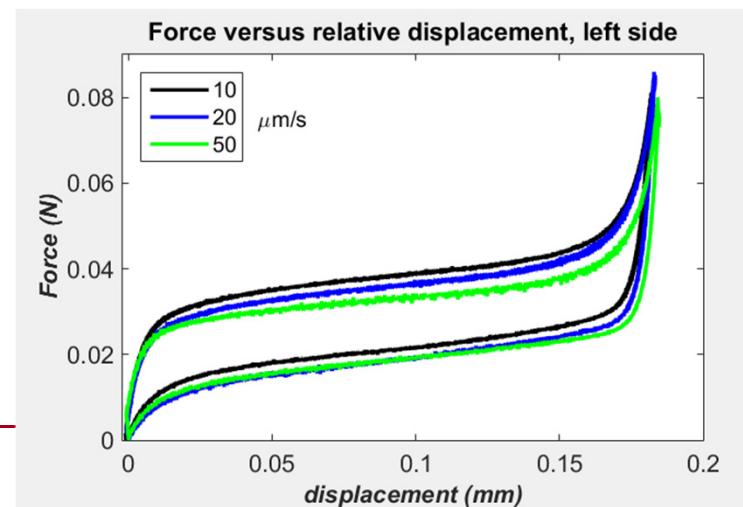


**ElastoViscoPlasticity**  
Glidcop Al-15 at  
different temperature

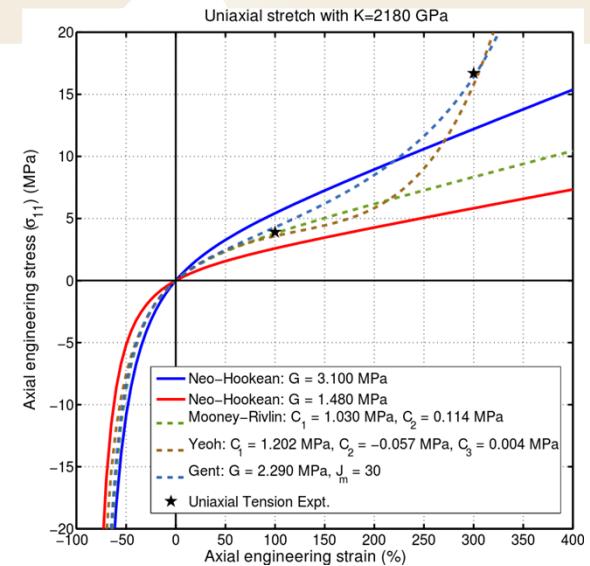
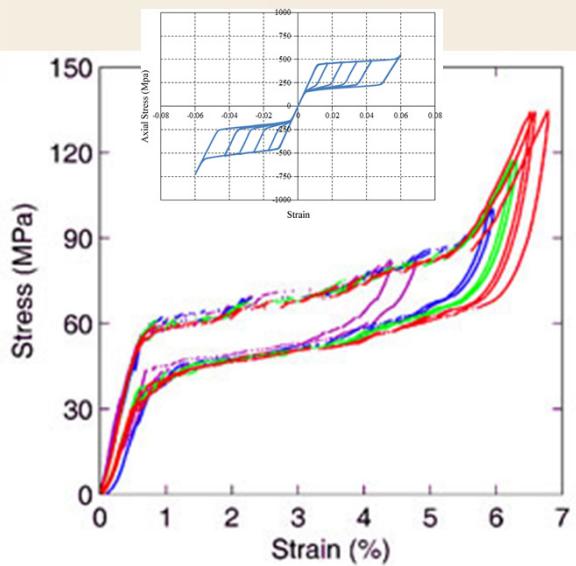
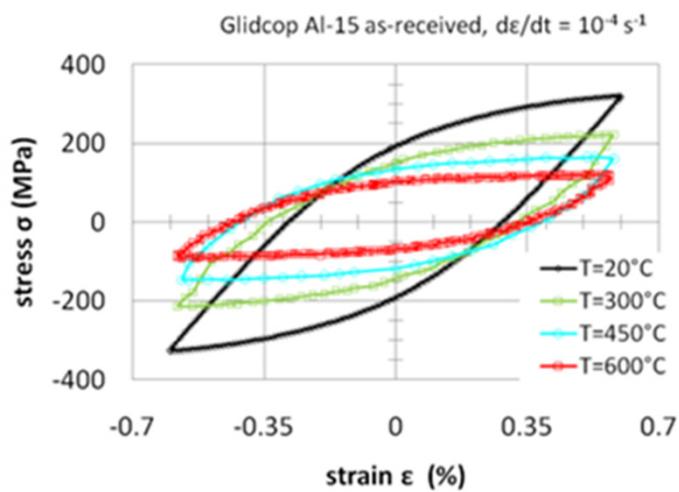
**Shear strain:100% ~ 400%**



**SuperElasticity**  
NiTi shape-memory  
alloys (SMAs)



# Which type of material model ?

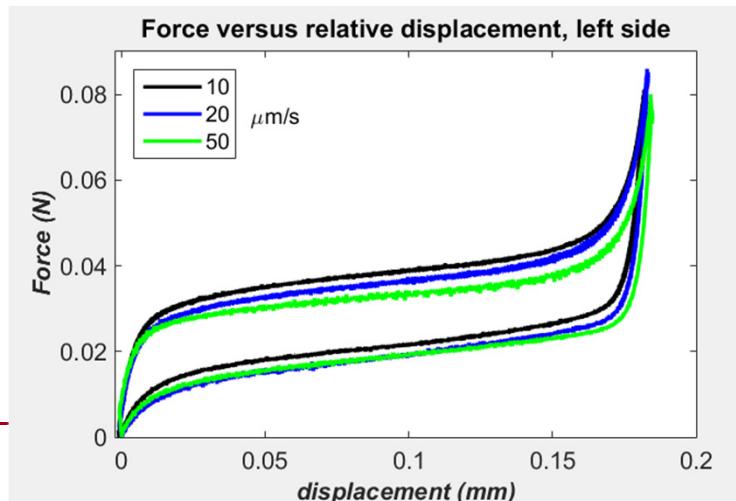


**ElastoViscoPlasticity**  
Glidcop Al-15 at  
different temperature

**SuperElasticity**  
NiTi shape-memory  
alloys (SMAs)

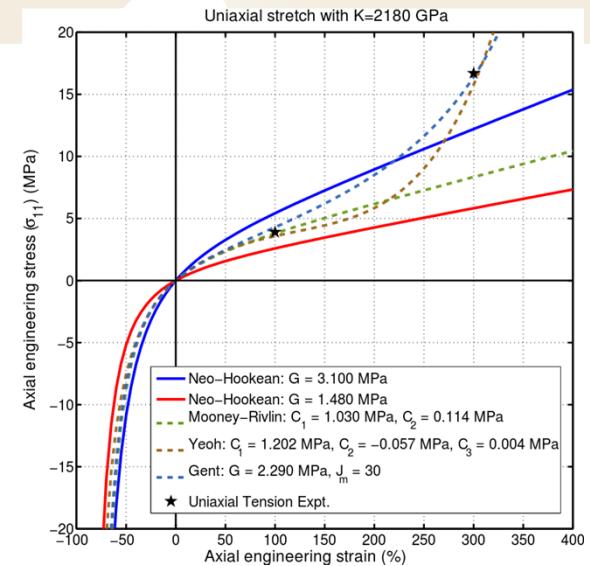
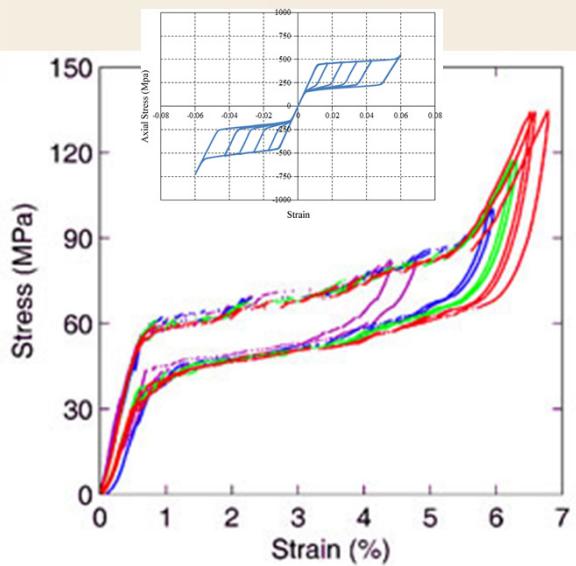
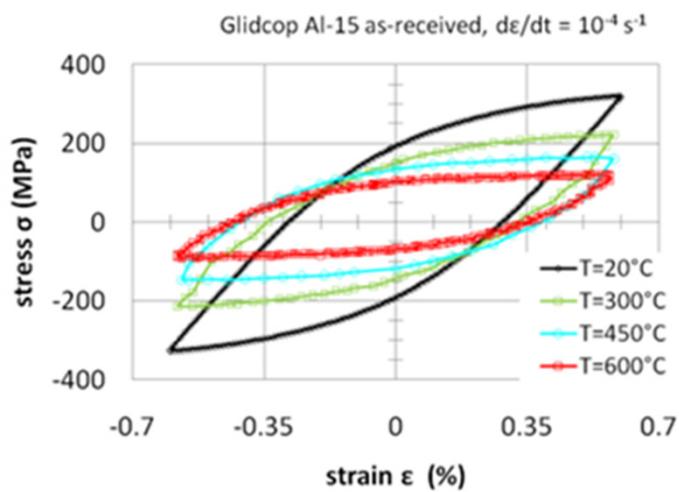
**HyperElasticity**  
rubber

**Shear strain:100% ~ 400%**



# Which type of material model ?

SLAC

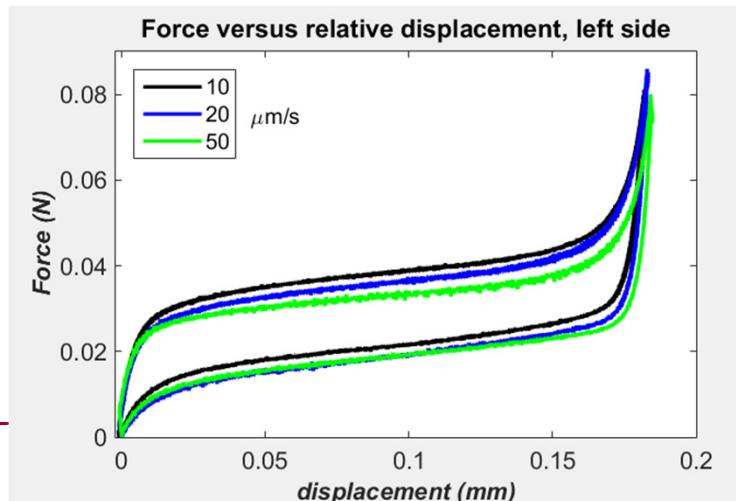


**ElastoViscoPlasticity**  
Glidcop Al-15 at  
different temperature

**SuperElasticity**  
NiTi shape-memory  
alloys (SMAs)

**HyperElasticity**  
rubber

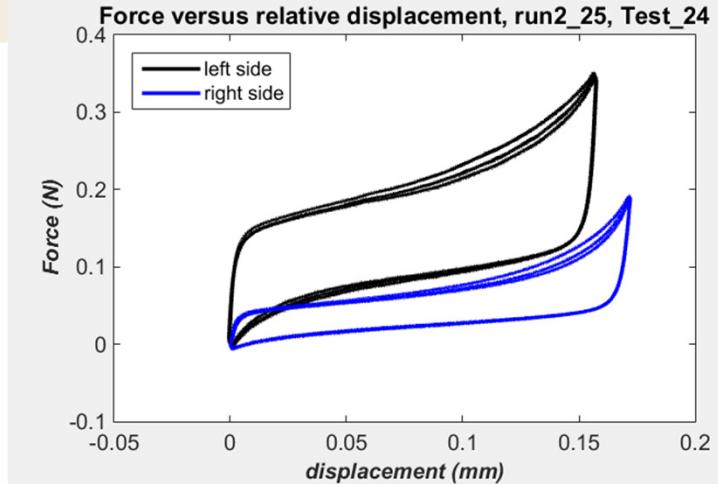
**Shear strain:100% ~ 400%**  
→ Full range FEA impossible (non convergent) with ANSYS



# Forces Analysis

## ➤ Mechanical constraint effects

- eGaN interface induced
  - Force  $F_{\text{GaN}} \sim 0.35 \text{ N/pad}$
  - $M_{\text{GaN}} \sim F_{\text{GaN}} (2*0.35+2*0.45) = 0.56 \text{ Nm}$
- Bending moments (30-mm thick mirror)
  - $M_{\text{bending}} \sim 0.3*90 = 27 \text{ Nm}$
- $M_{\text{GaN}} / M_{\text{bending}} \sim 2\% \text{ (very significant)}$



## ➤ eGaN Viscosity related force

- $F_{\text{viscosity}} \sim 0.4 \mu\text{N/pad}$
- $F_{\text{viscosity}} / F_{\text{measured}} \sim 10^{-6} \text{ (negligible)}$

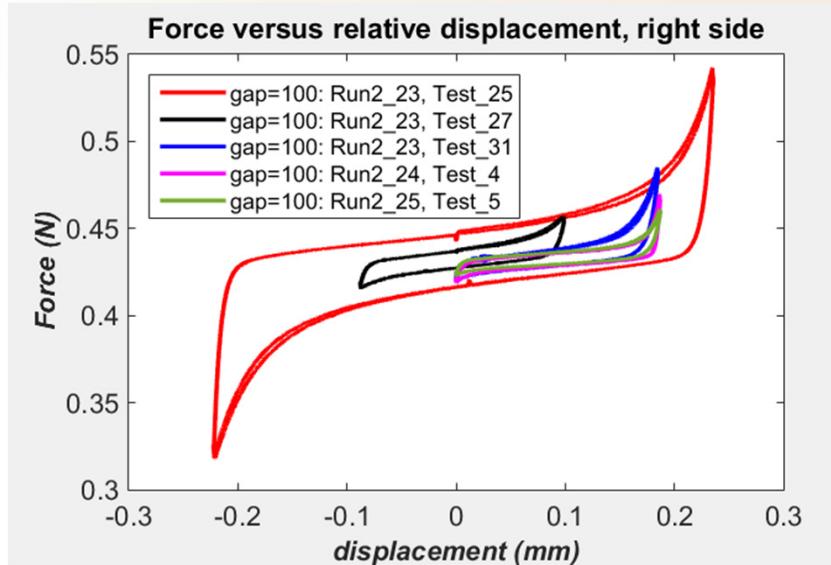
$$F_{\text{viscosity}} = A\mu \frac{\partial V}{\partial y}$$

$g_{\text{GaN}} = 50 \mu\text{m}$

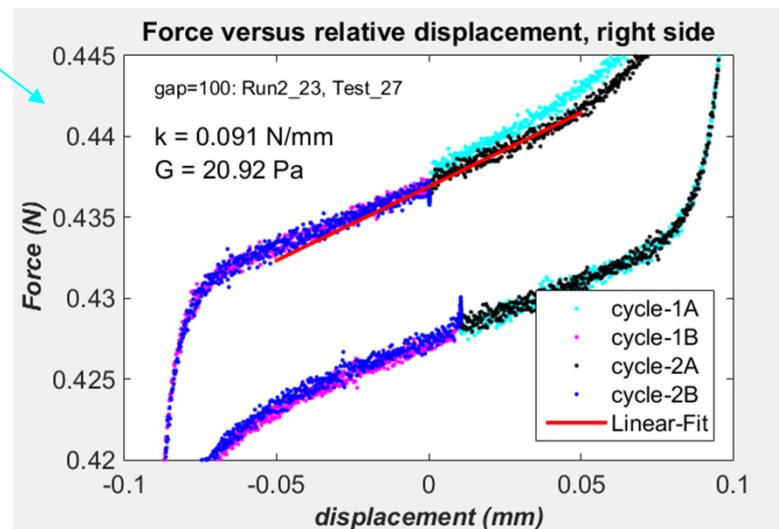
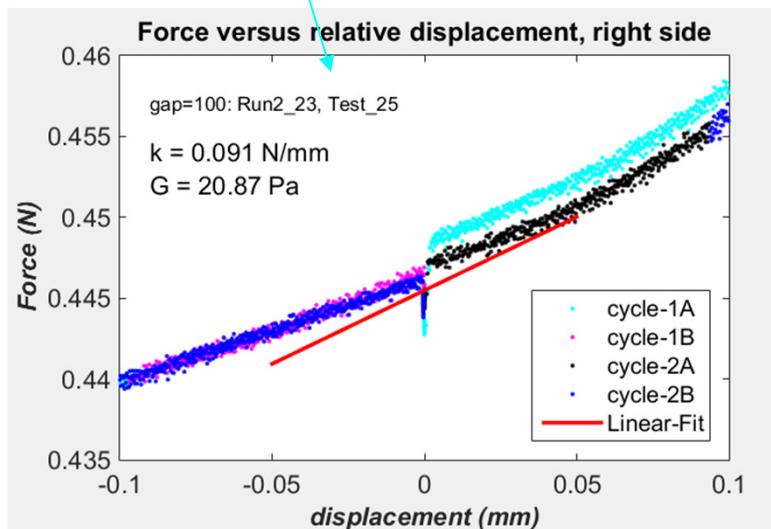
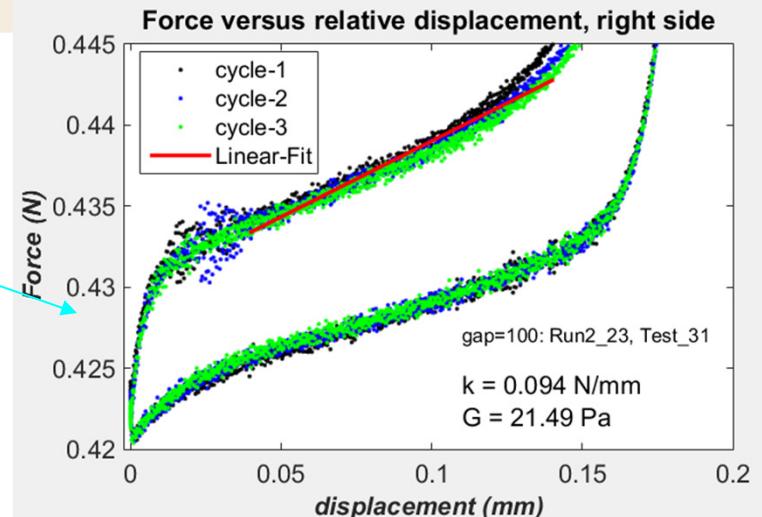
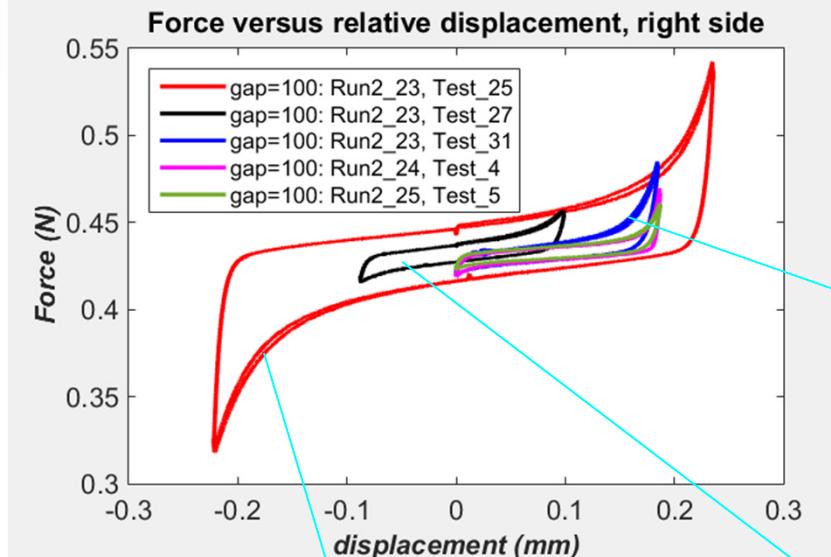
- The mechanical constraint effects of eGaN interface is **not negligible (at this stage)**, but it's not **viscosity related force** (and therefore will not be treated as fluid)

# GaN Test results – Data fitting, modulus

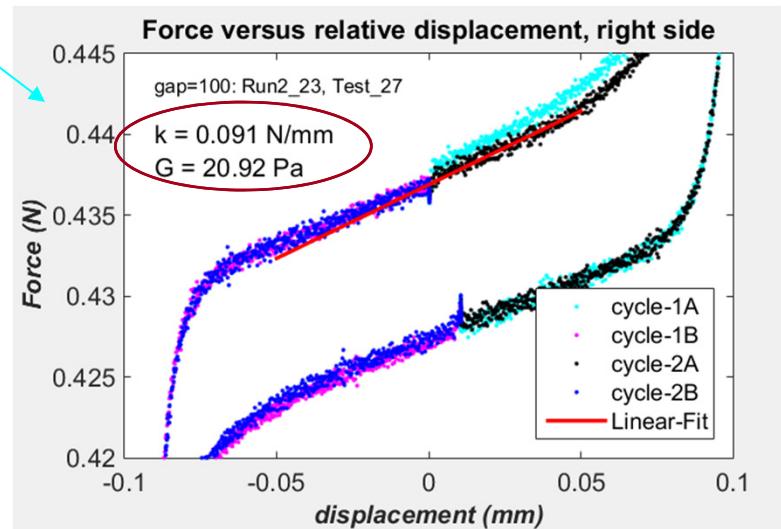
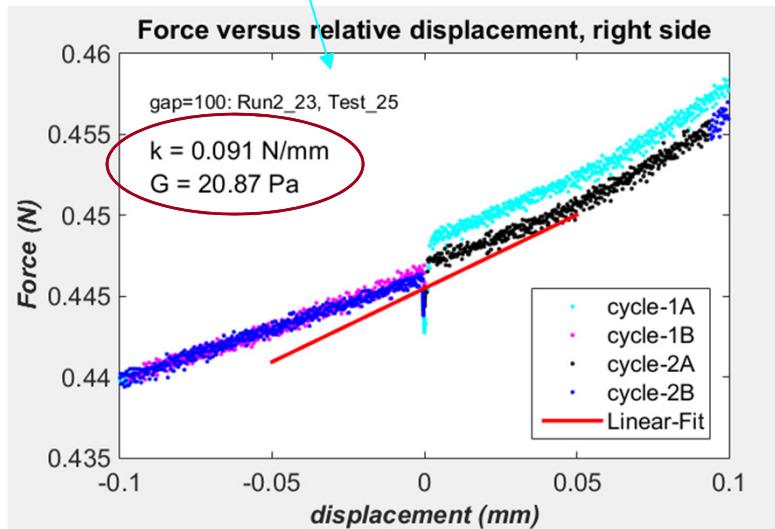
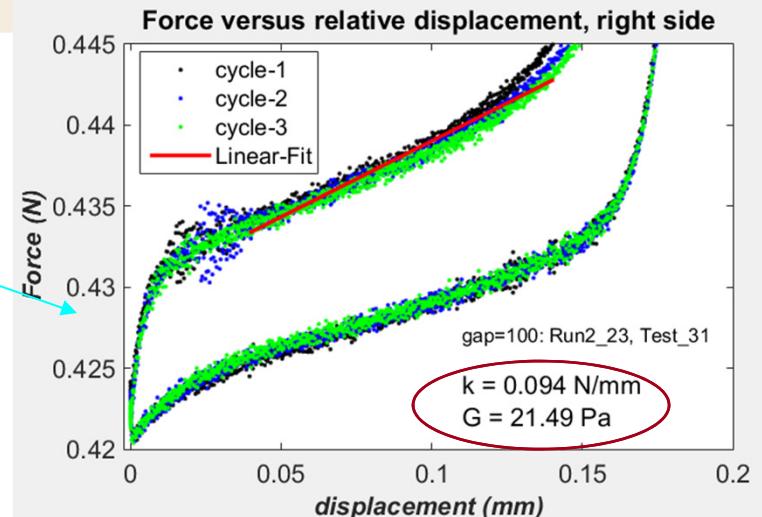
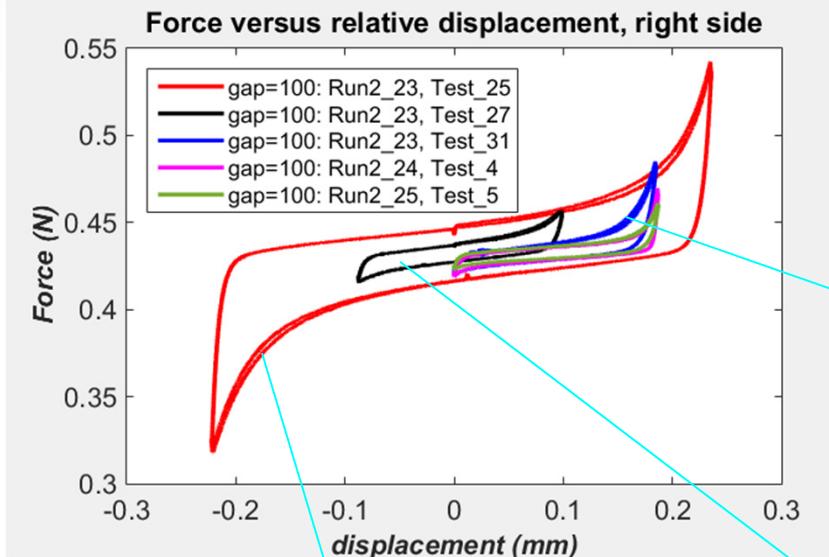
SLAC



# GaN Test results – Data fitting, modulus

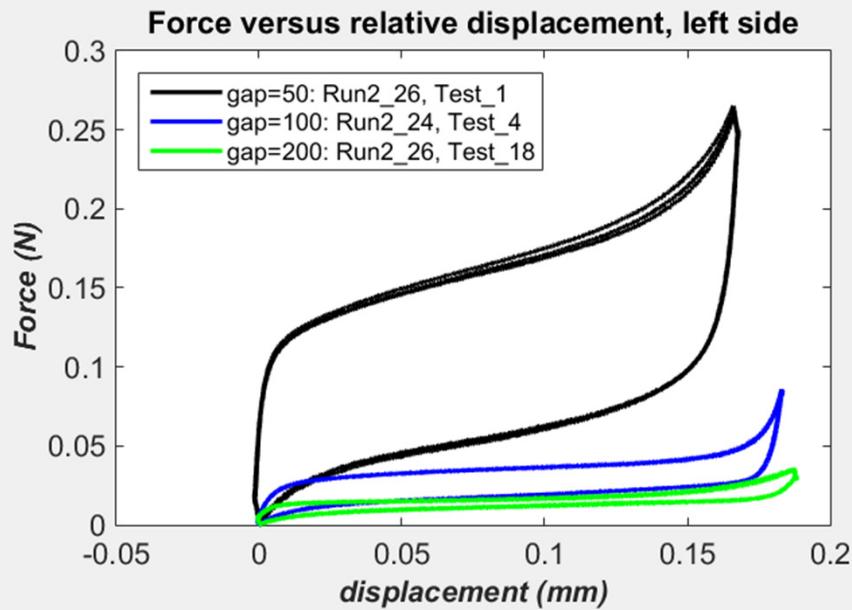


# GaN Test results – Data fitting, modulus



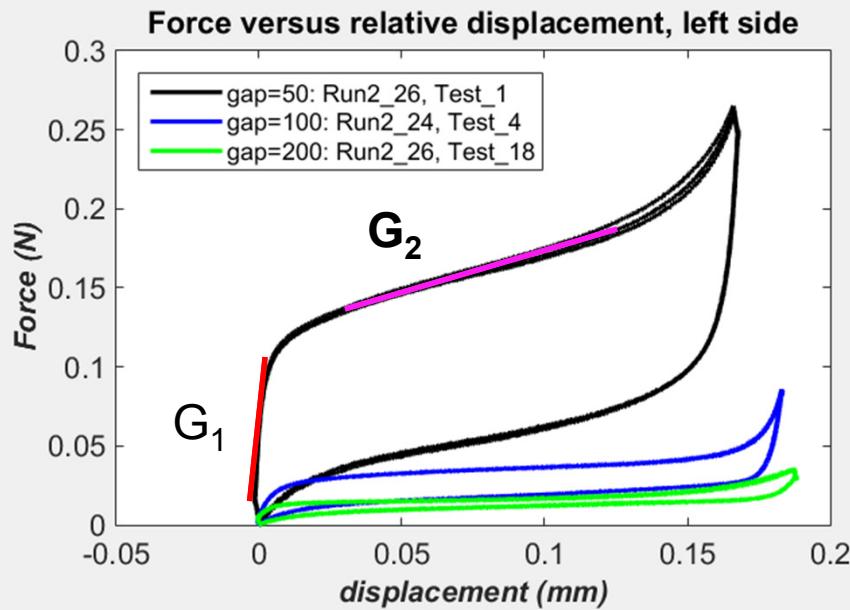
# GaN test results – gap dependant; Modulus G<sub>1</sub> and G<sub>2</sub>

SLAC



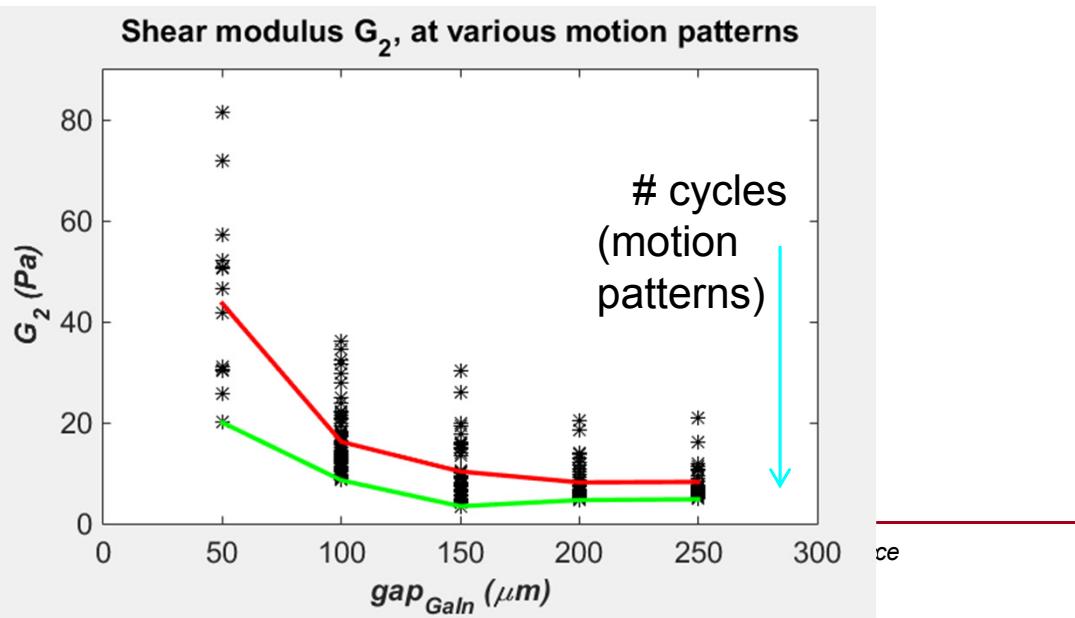
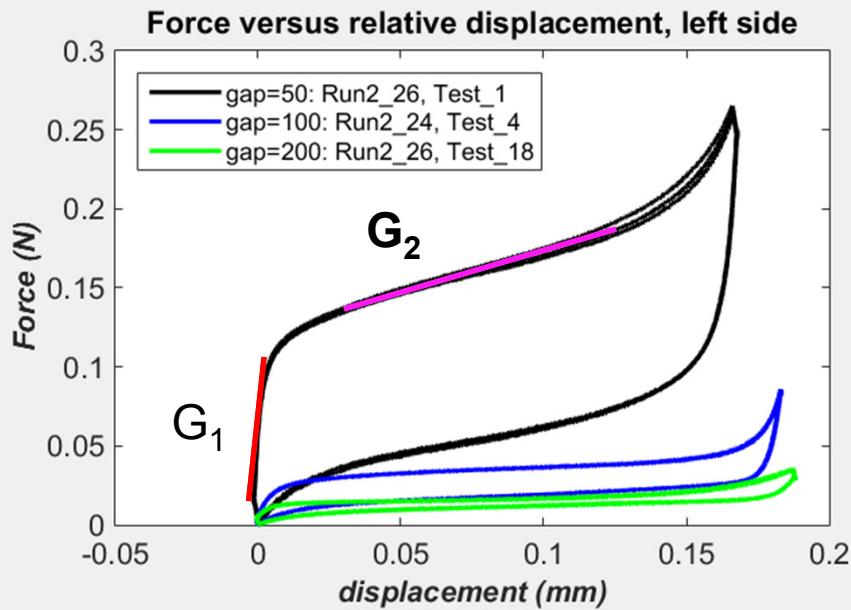
# GaN test results – gap dependant; Modulus $G_1$ and $G_2$

SLAC



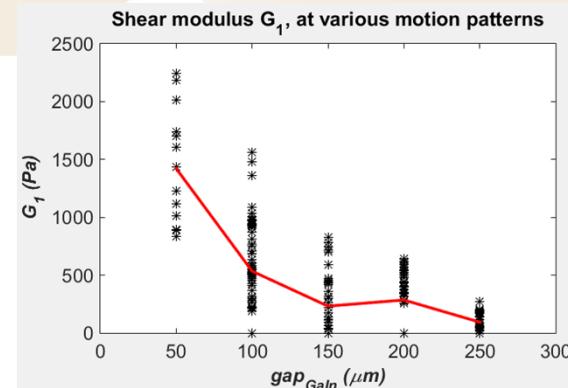
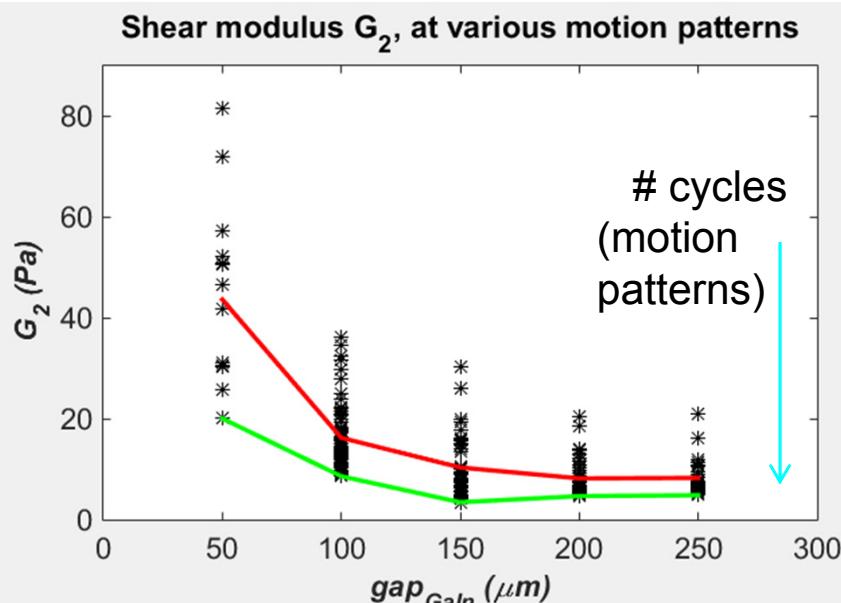
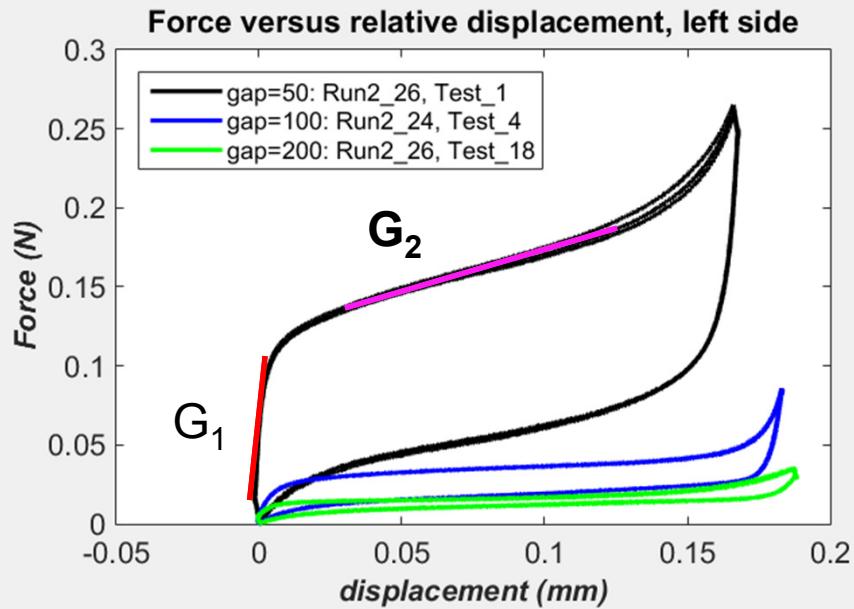
# GaN test results – gap dependant; Modulus $G_1$ and $G_2$

SLAC



# GaN test results – gap dependant; Modulus $G_1$ and $G_2$

SLAC

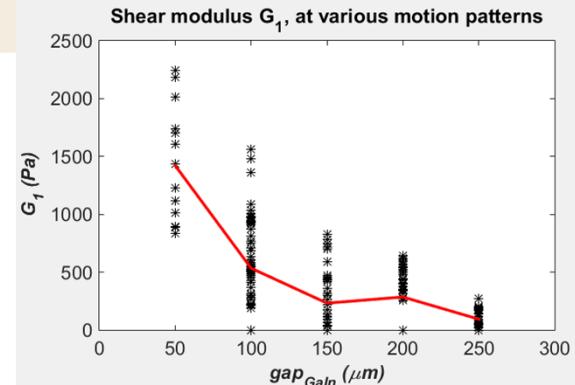
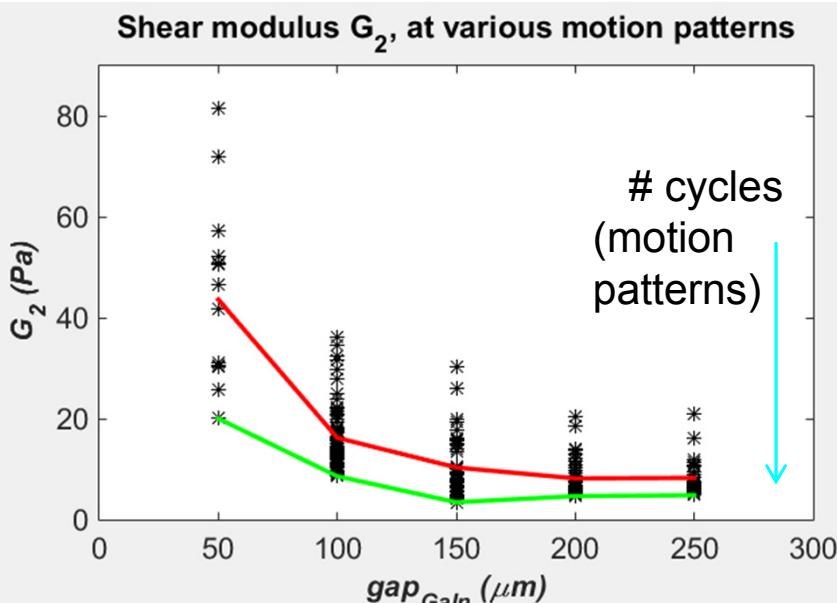
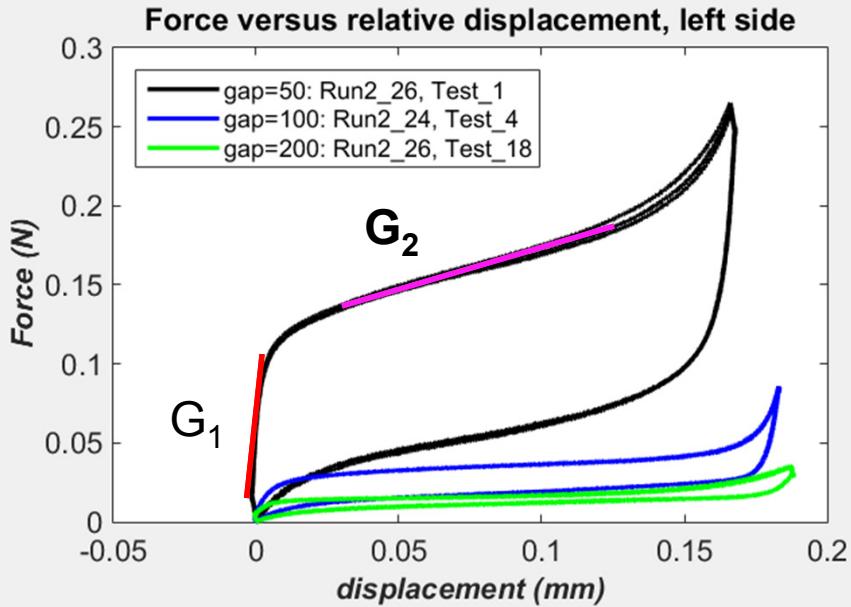


Shear modulus  $G$  of GaN interface

gap	$G_2$ _av	$G_2$ _min	$G_1$
$\mu m$	Pa	Pa	Pa
50	43.7	20.0	1421
100	16.2	8.6	534
150	10.3	<b>3.4</b>	232
200	<b>8.2</b>	<b>4.7</b>	285
250	<b>8.3</b>	<b>4.8</b>	94

# GaN test results – gap dependant; Modulus $G_1$ and $G_2$

SLAC



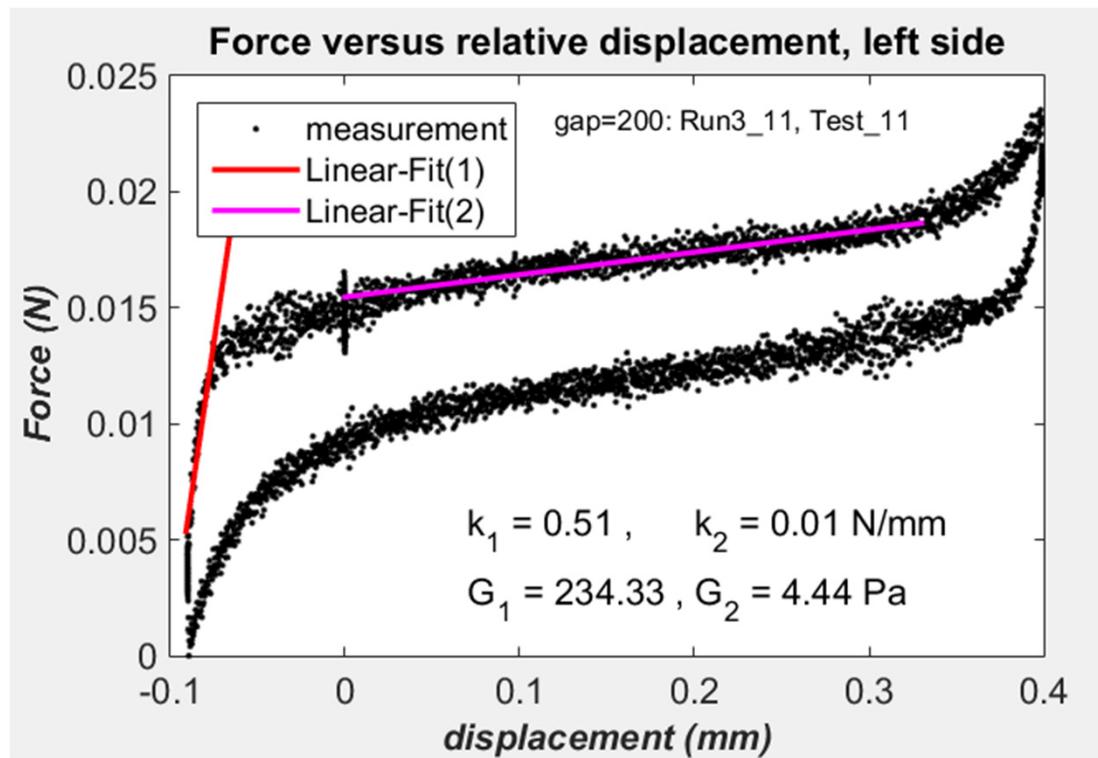
**Shear modulus  $G$  of GaN interface**

gap	$G_2$ _av	$G_2$ _min	$G_1$
$\mu m$	Pa	Pa	Pa
50	43.7	20.0	1421
100	16.2	8.6	534
150	10.3	3.4	232
200	8.2	4.7	285
250	8.3	4.8	94

**$G_2 = 9$  Pa**

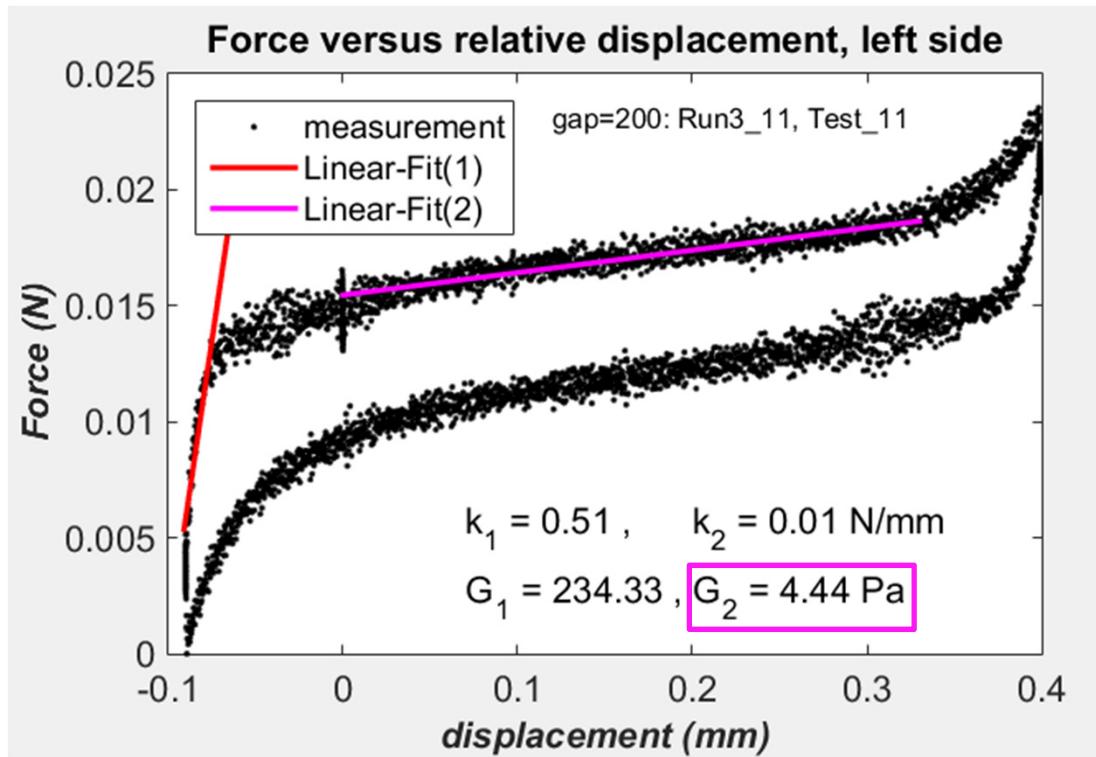
# Bending Operation Optimization with Galn Interface

SLAC



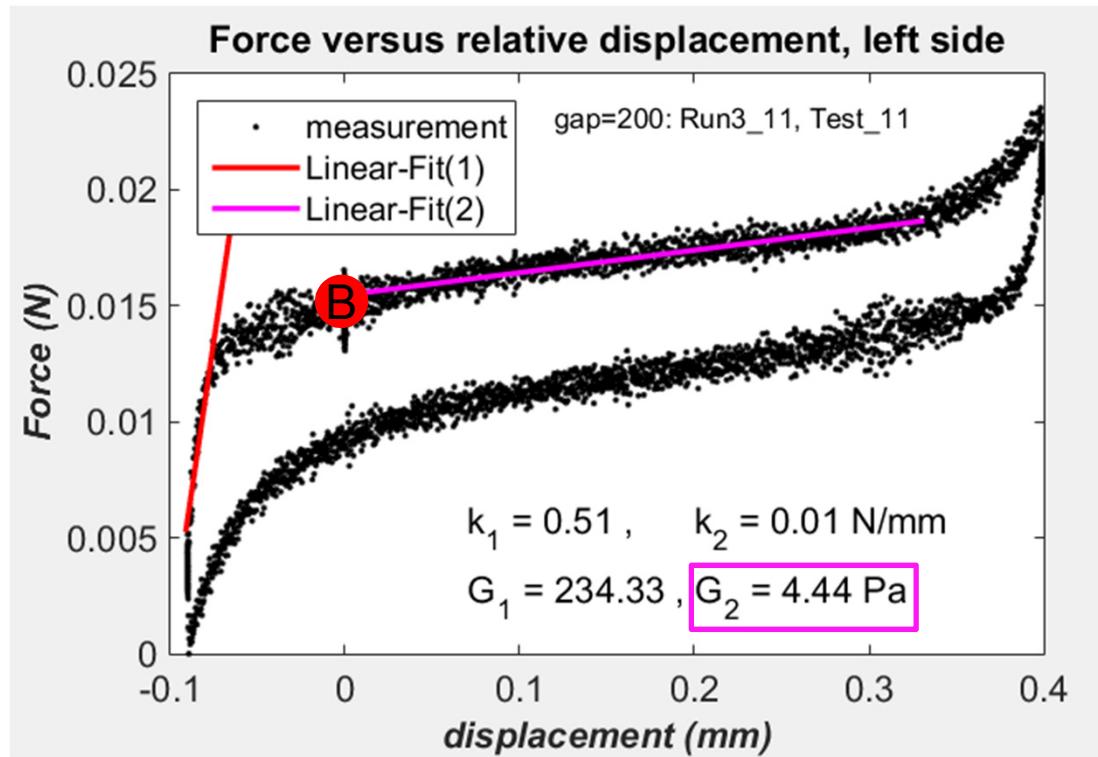
# Bending Operation Optimization with Galn Interface

SLAC



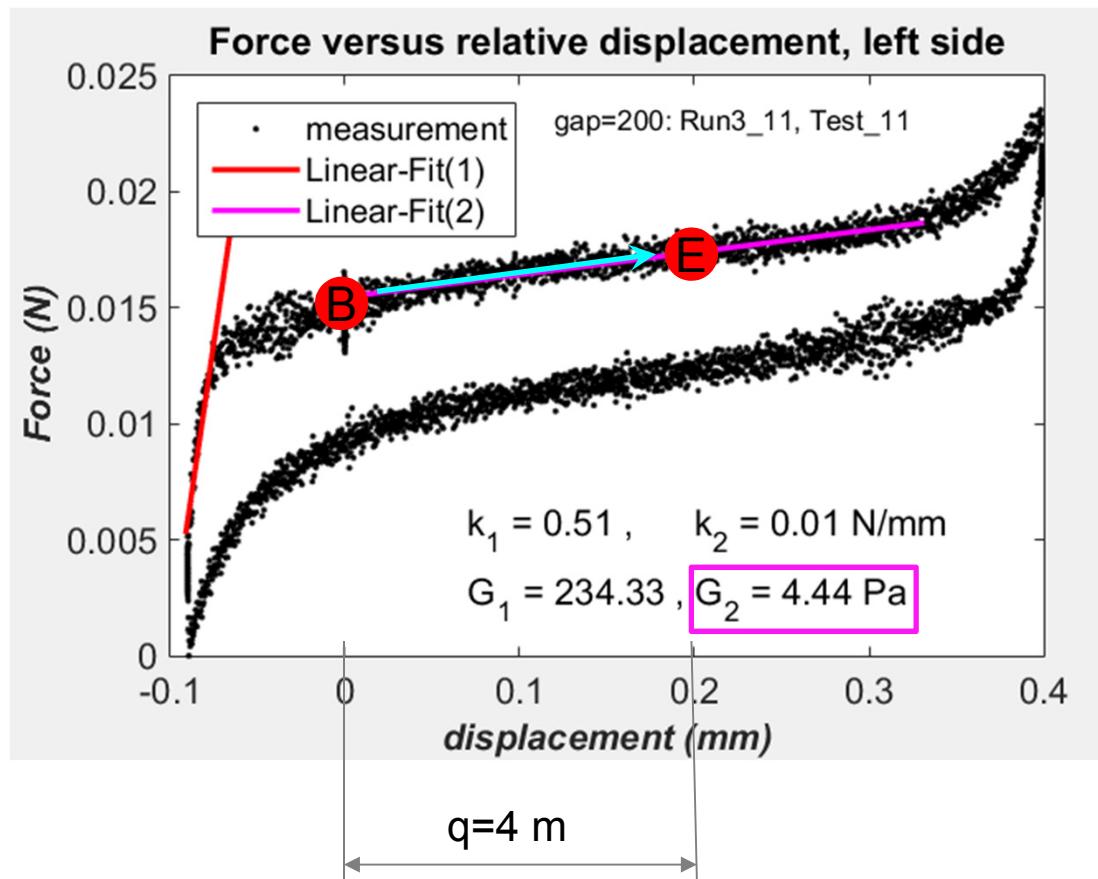
# Bending Operation Optimization with Galn Interface

SLAC



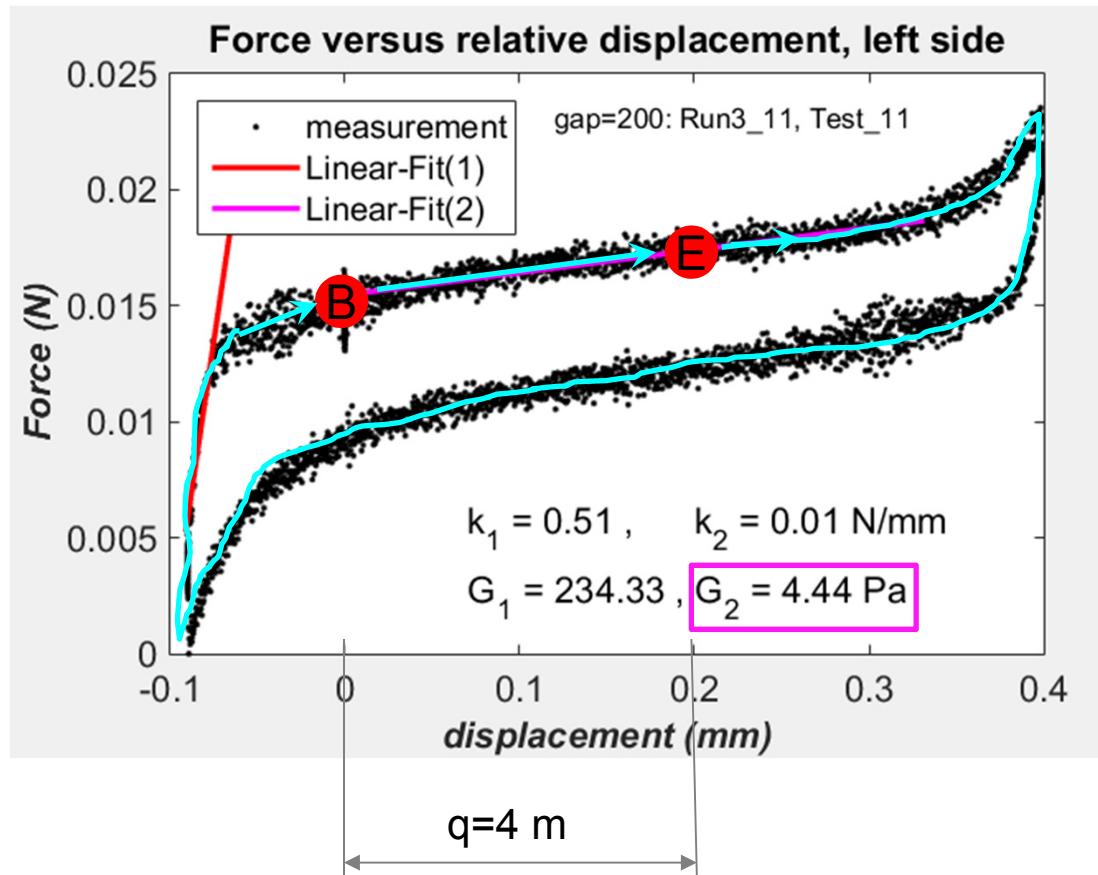
# Bending Operation Optimization with Galn Interface

SLAC



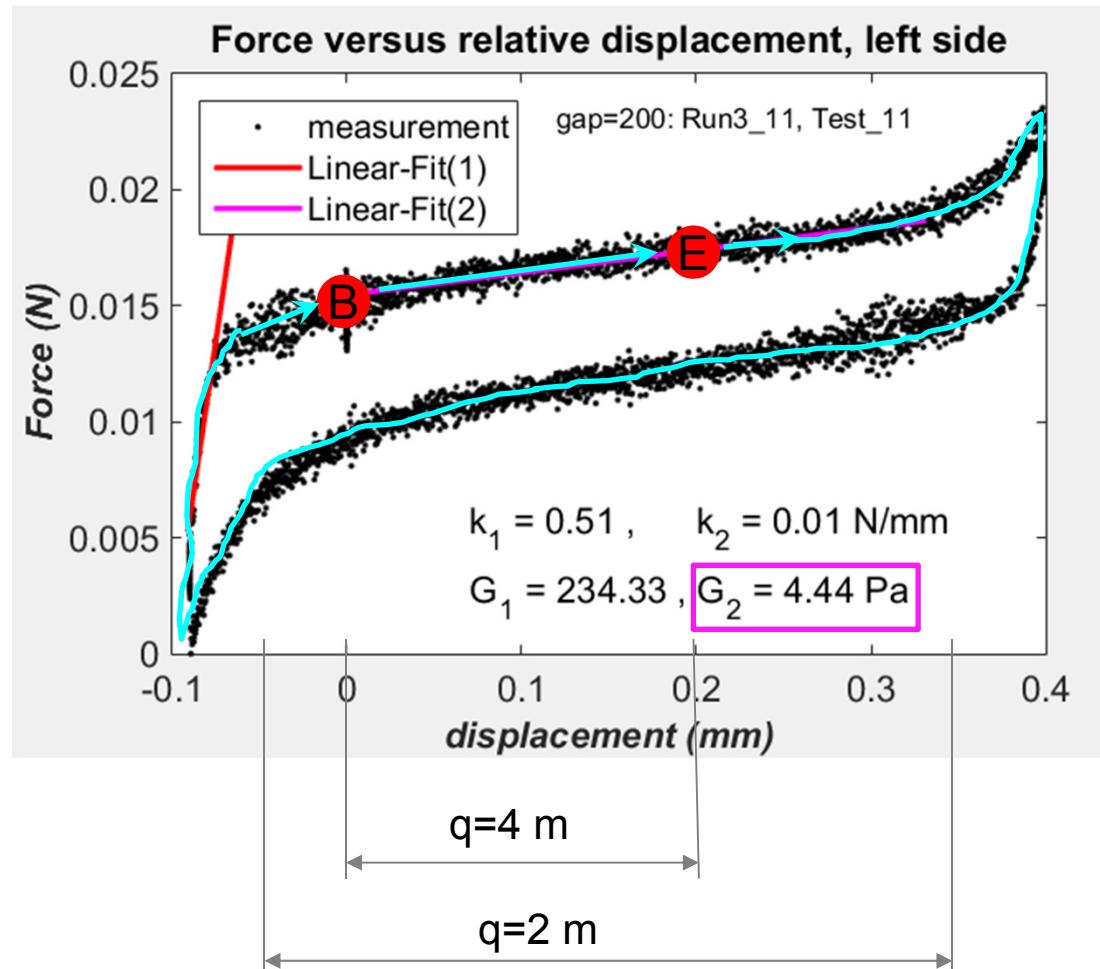
# Bending Operation Optimization with Galn Interface

SLAC



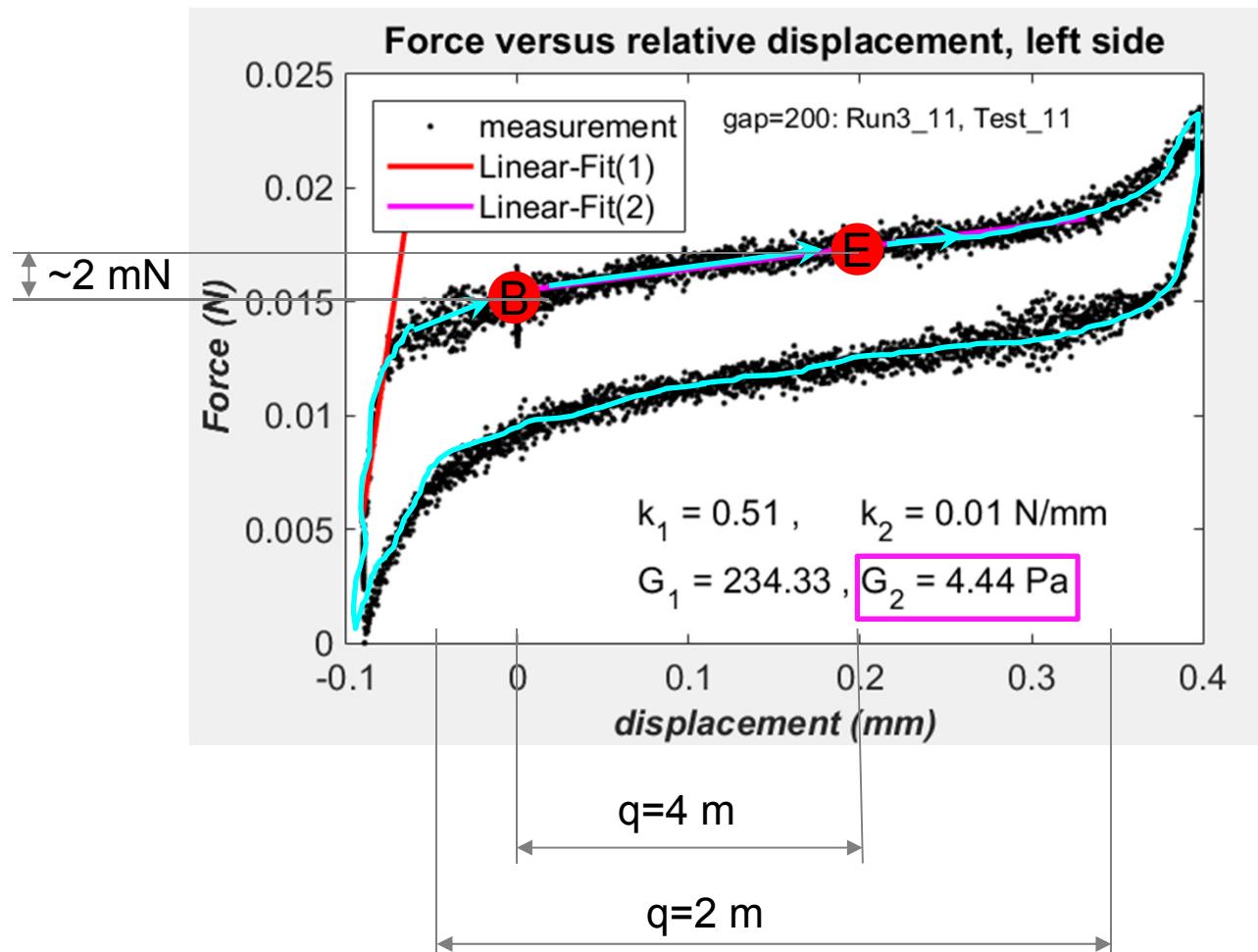
# Bending Operation Optimization with Galn Interface

SLAC



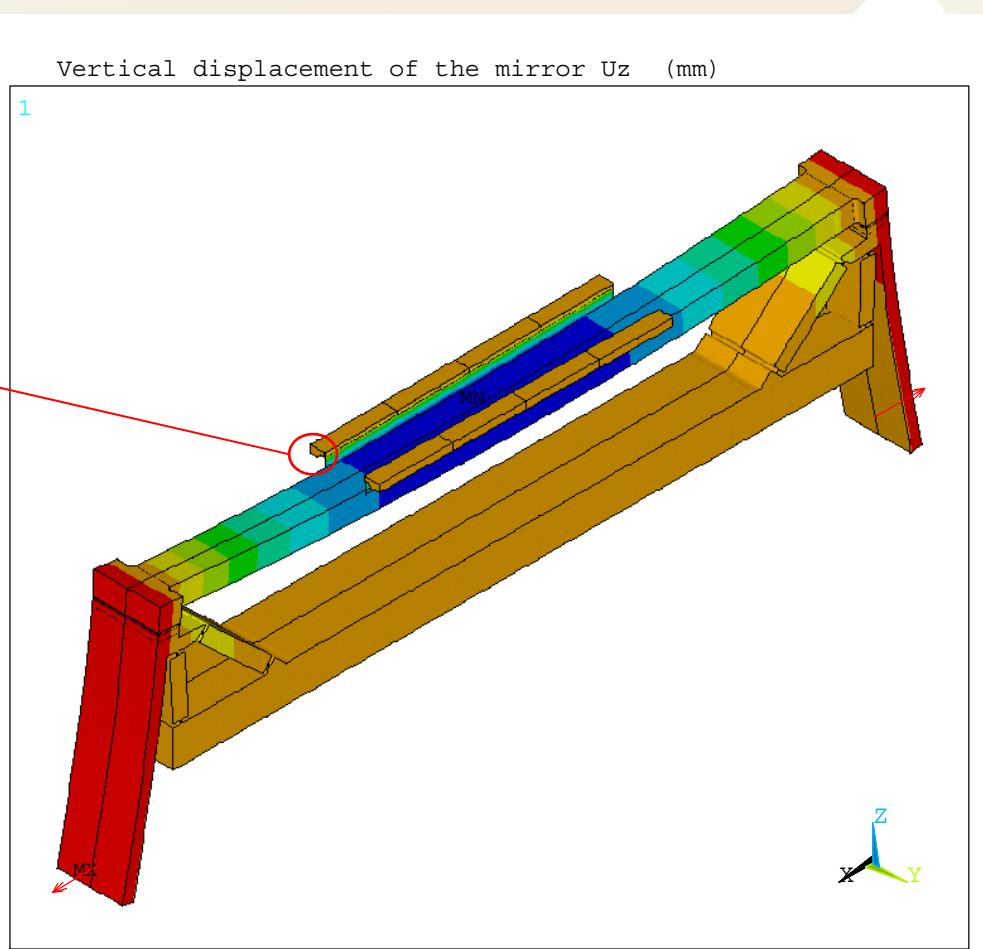
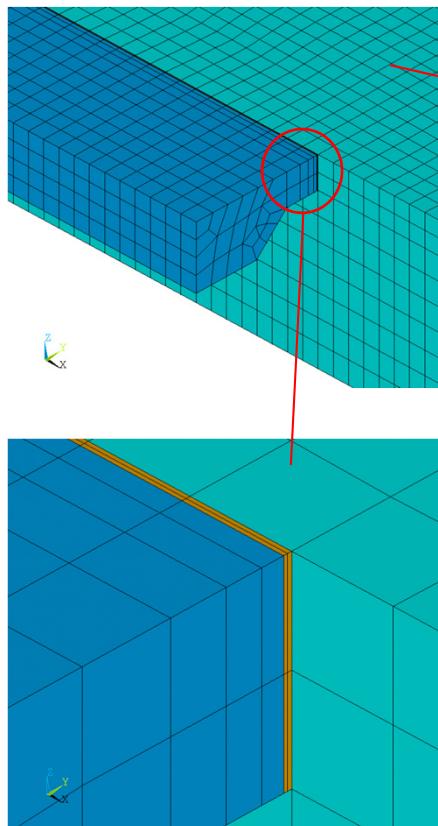
# Bending Operation Optimization with Galn Interface

SLAC



# FEA results with cooling blocks and GaIn interface

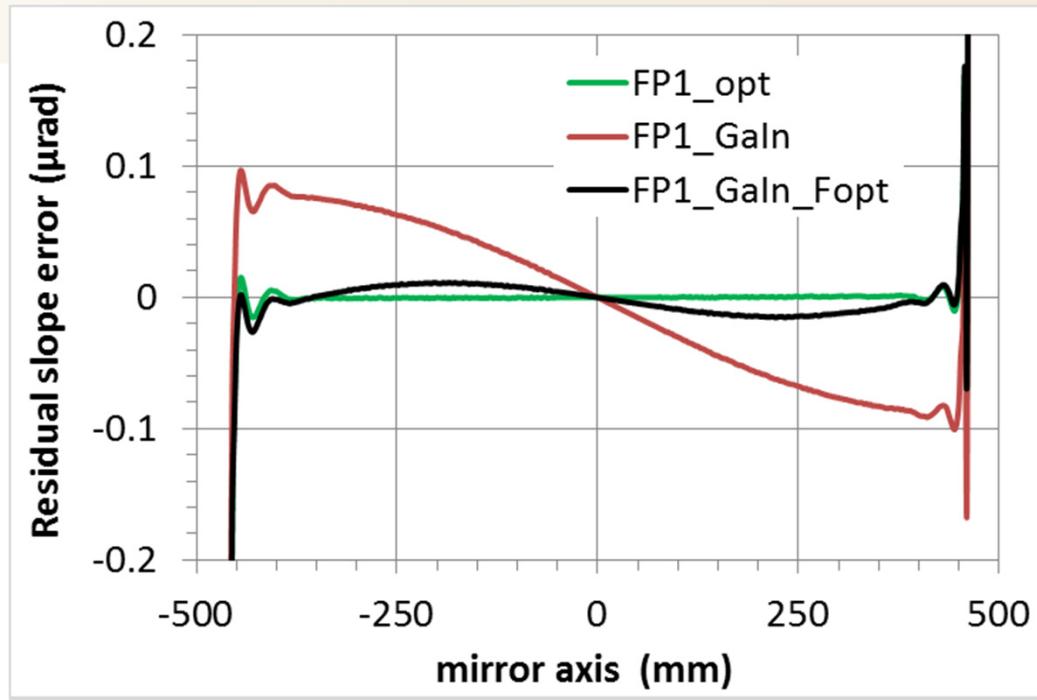
SLAC



$$G_2=9 \text{ Pa}$$

# FEA results with cooling blocks and Galn interface

SLAC

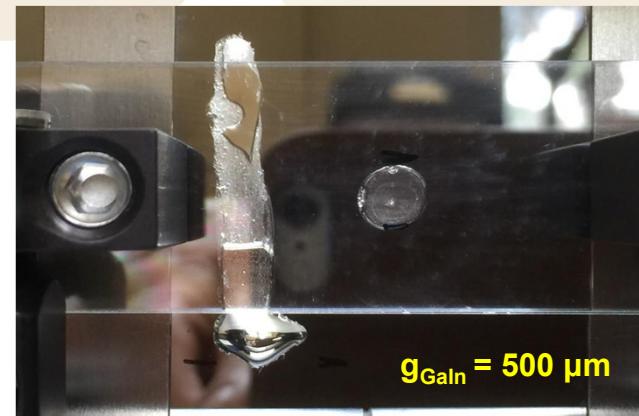
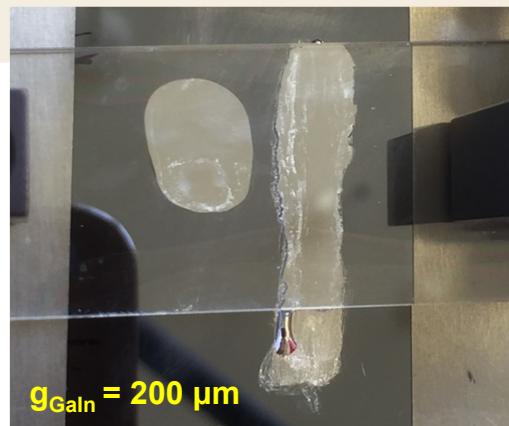
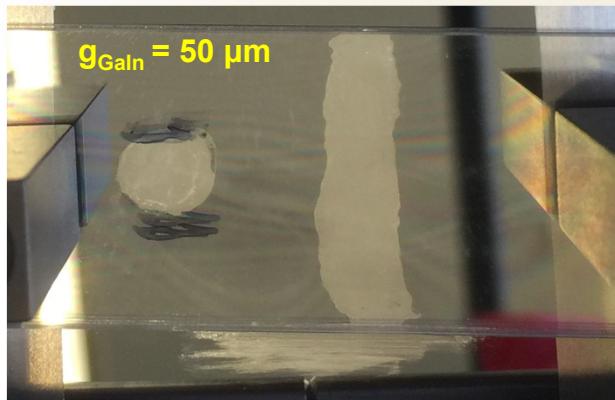


**Residual Slope Error (RSE) :**

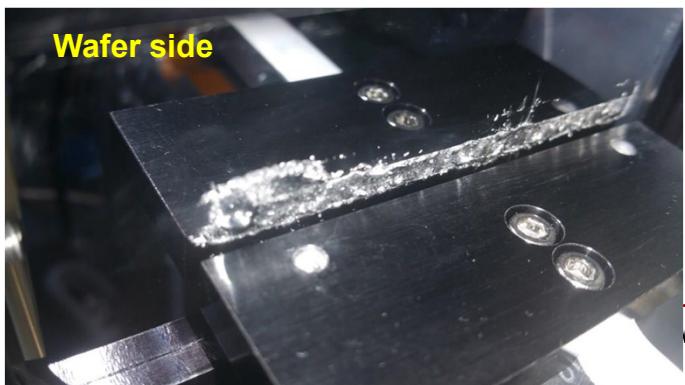
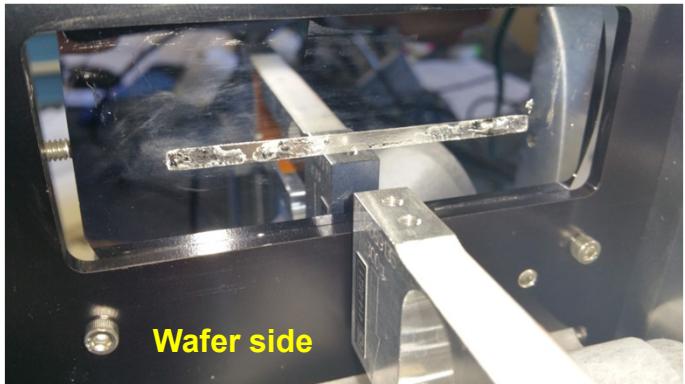
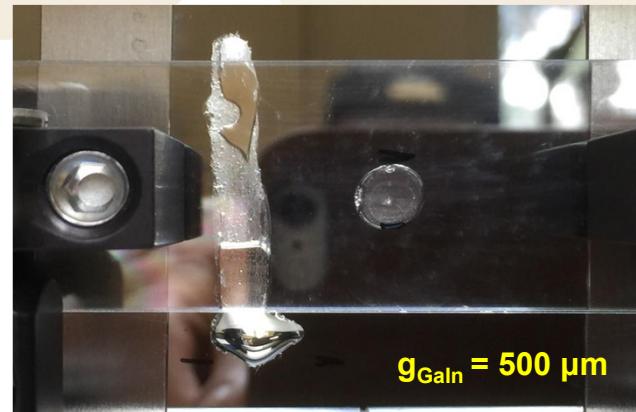
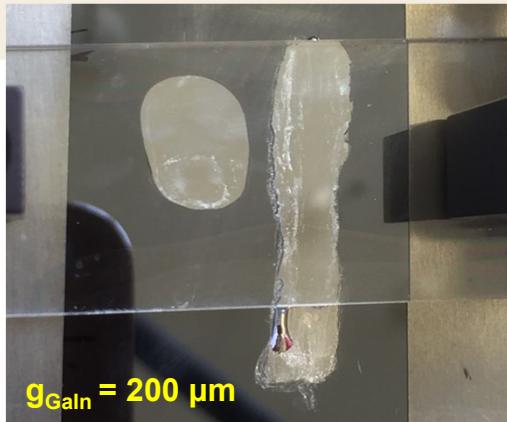
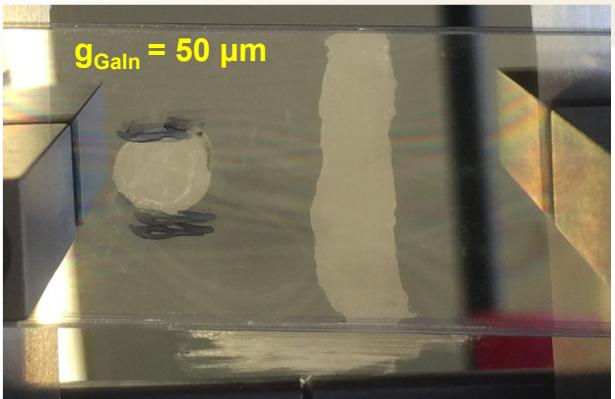
$$\Delta \text{slope} = \text{slope} - \text{slope}_{\text{ellipse}}$$

$Uz_{BC}$	$F_{Galn}$	$g_{Galn}$	$G_2$	$q$	$F_{inp}$	$F_{outp}$	$RMS_{dUz}$	$RMS_{dsip}$
$\mu m$	$mN$	$\mu m$	$Pa$	$m$	$N$	$N$	$nm$	$nrad$
0	-13.7	200	9	4.7	90	90	0.4	1
0	-13.7	200	9	4.7	90.014	90.011	10.0	57
							1.8	9

# GaN gaps



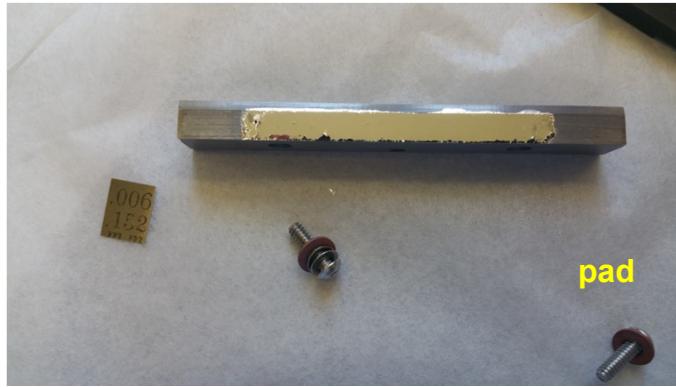
# GaN gaps



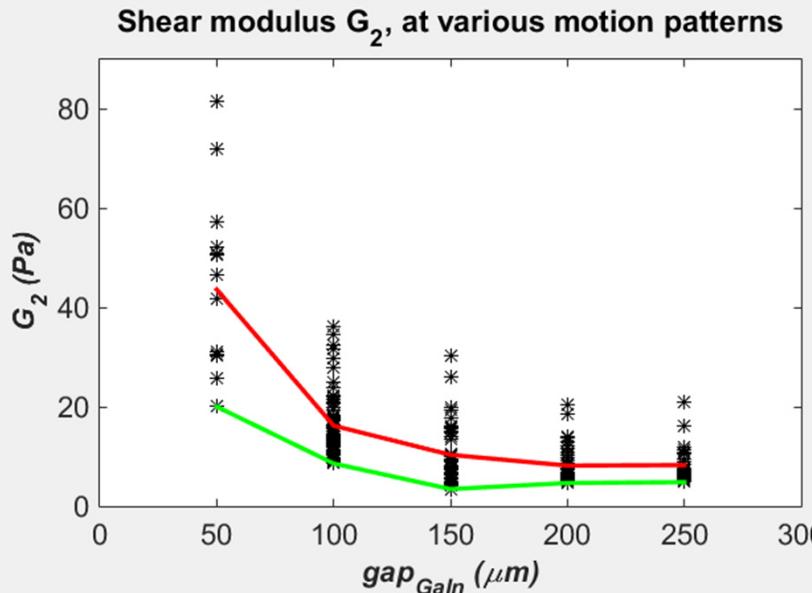
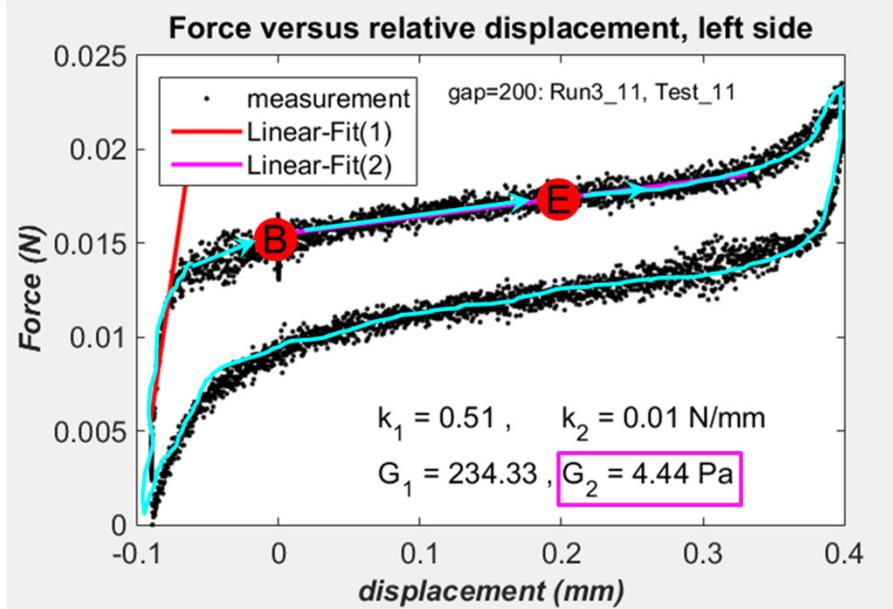
Before assembling  
for test at  $g_{\text{GaN}} =$   
 $152 \mu\text{m}$

After test at  
 $g_{\text{GaN}} = 152 \mu\text{m}$

In as thermal interface



# Summary of Galn test results



- The mechanical constraint effects of Galn contact interface can be minimized to be negligible for LCLS-II SXR KB mirrors by
  - Setting the  $\text{g}_{\text{Galn}} = 150 \mu\text{m}$ . Shear modulus  $G_2 = 9 \text{ Pa}$  easily achievable
  - Operating between point B and E, and following the force ~ displacement curve

# Acknowledgement

SLAC

- **Daniele Harrington** SLAC/SSRL
- **Tom Rabedeau** SLAC/SSRL
- **Eliazar Ortiz** SLAC/LCLS-II
- **Venkat Srinivasan** SLAC/LCLS, now India
- **Peter Stefan** SLAC/LCLS